

Additive Manufacturing – versatile but challenging process

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Fabrication of three dimensional objects

Additive Manufacturing, Rapid Prototyping, Free Form Fabrication, Laser 3D Structuring



Additive Manufacturing (bottom-up approach)

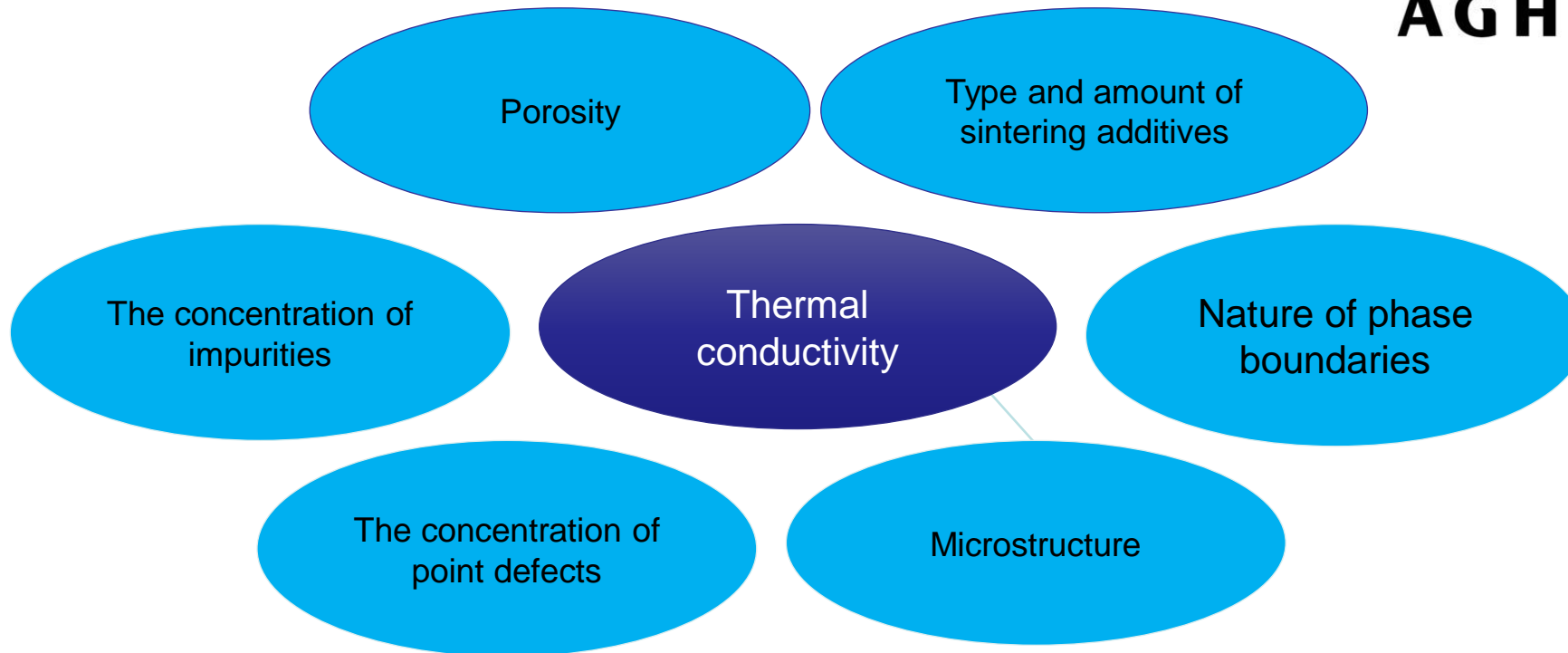
| | Additive Manufacturing | Physico-chemical processes |
|----|---|------------------------------------|
| 1) | Fused Deposition Modeling (FDM) (Polimers) | metling and UV-curring |
| 2) | Stereolitography (SLA) Digital Light Processing (DLP) | UV-curring |
| 3) | Laminated Object Manufacturing (LOM) (celuloze polimers) | Thermolisis and hardening polimers |
| 4) | 3D Colour Jet Printing (3CJP) (gypsum) | Hydration reaction of gypsum |
| 5) | Selective Laser Sintering (SLS) (ceramic and metallic powders) | Sintering |
| 6) | Laser Engineering Net Shaping (LENS) (ceramic and metallic powders) | Sintering |
| 7) | „Clading” Laser Metal Deposition LMD (metallic powders) | Metllting and crystallization |

Laser Processing Top-down approach

| Additive Manufacturing | Physico-chemical processes |
|-------------------------------------|--|
| Laser Ablation | Sublimation and evaporation of ceramic and |
| Laser cutting, Scratching, Drilling | Thermall dyssoication evaporation |

High thermal conductivity materials

microstructural aspects:



Aluminum nitride is a material of great application potential:
thermal conductivity of about 260W/mK,
broadband insulator 6,2 eV
piezoelectric properties, the thermal expansion coefficient close to silicon

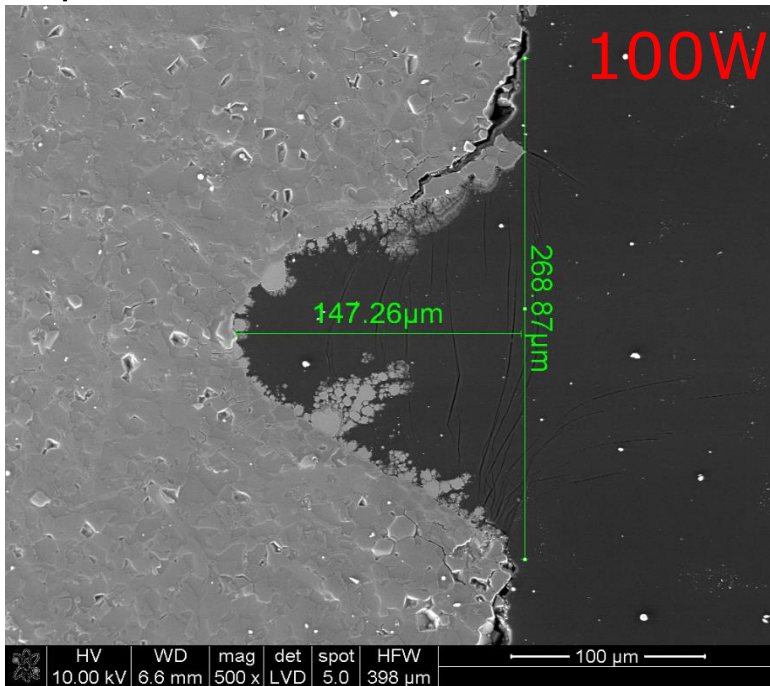
Diamond is the material of the future:
thermal conductivity of about 2000W/mK,
electrical insulator, hardness 36 GPa,
As an additive to composites it can replace the tungsten carbide used in cutting tools

3D Shaping of AlN micro heat exchanger

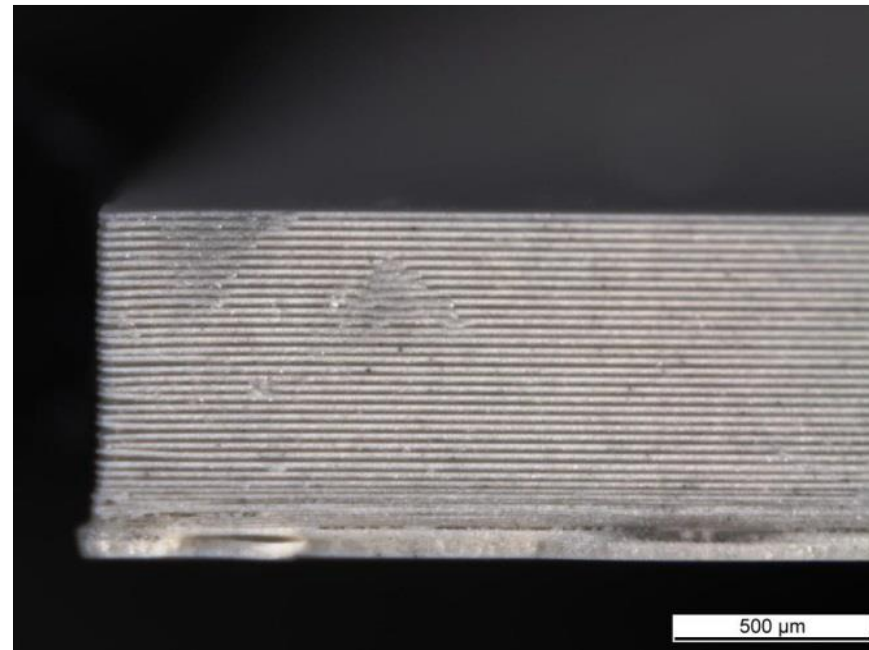
a) Laser processing; b) Digital light processing



a)



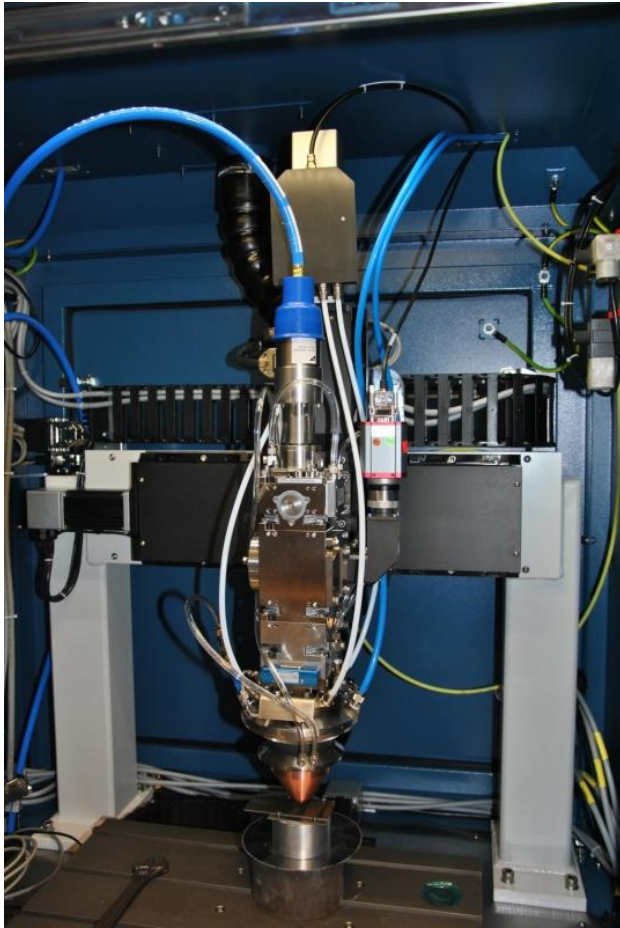
b)



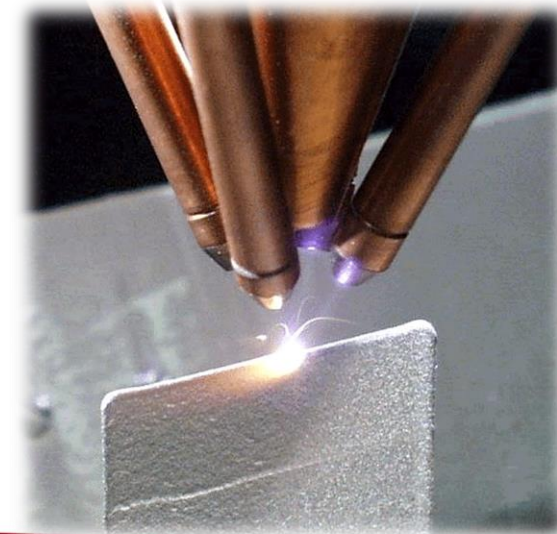
Aluminum nitride (AlN) offers remarkable thermal conductivity which makes it suitable candidate in manufacturing of high-tech heat exchangers. The present work aims to 3D shaping of a micro-sized heat exchanger made of AlN.

Paulina Ożóg PhD thesis „Shaping of AlN powders by Additive Manufacturing applying UV-curable dispersions” AGH and EMPA 2019 supervisors: Prof. D. Kata, Prof. T. Graule.

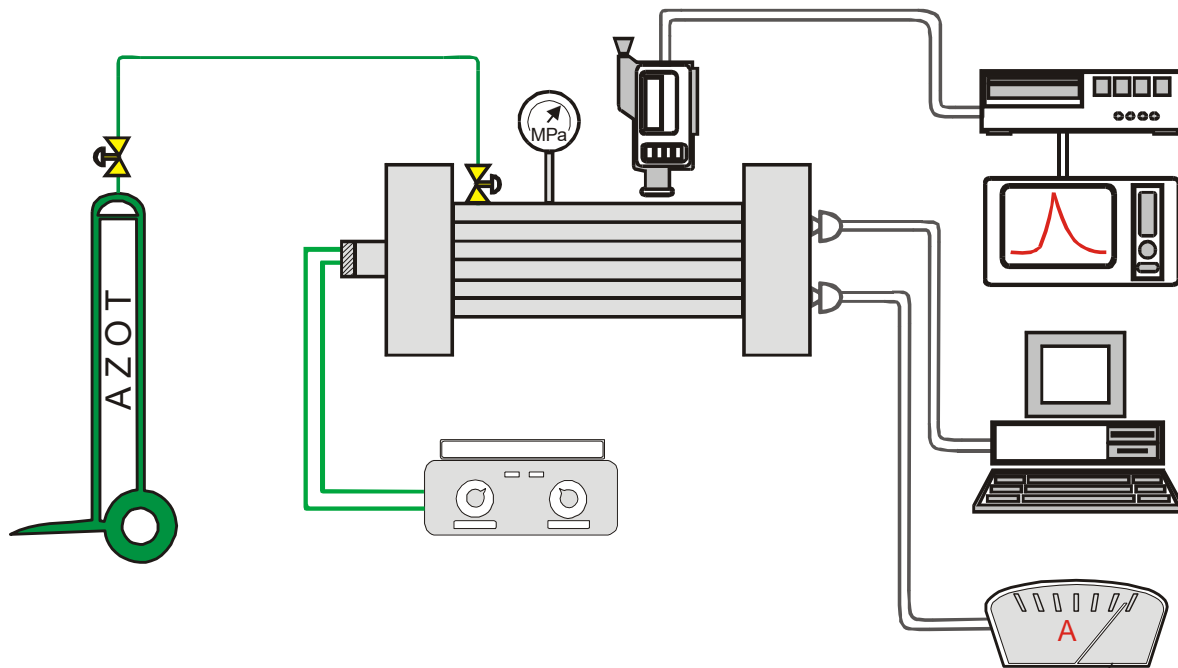
Additive Manufacturing of AlN and AlN-GPLs composites



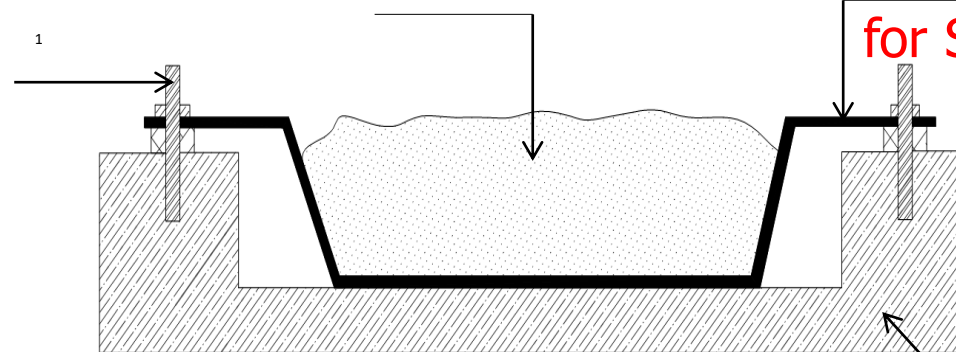
1. Hybrid apparatus for laser cladding, surface ablation, welding, cutting and SHS reactions
2. JK2000FL equipped with ytterbium doped wire fiber
3. Laser beam with wavelength of $1063[\text{nm}] \pm 10[\text{nm}]$



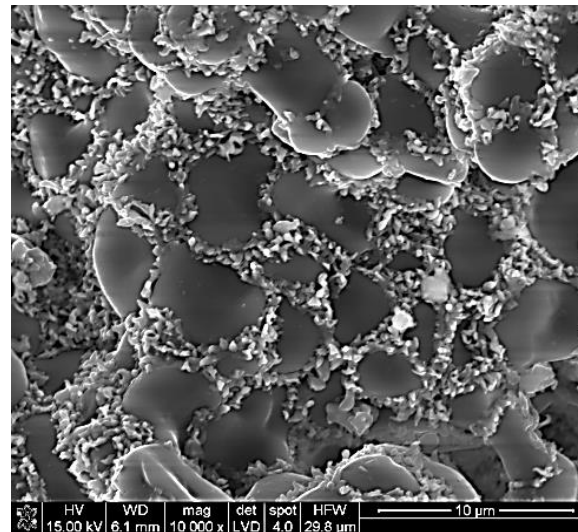
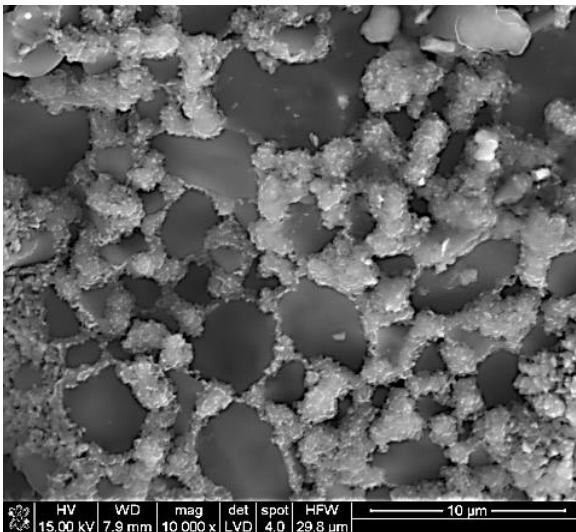
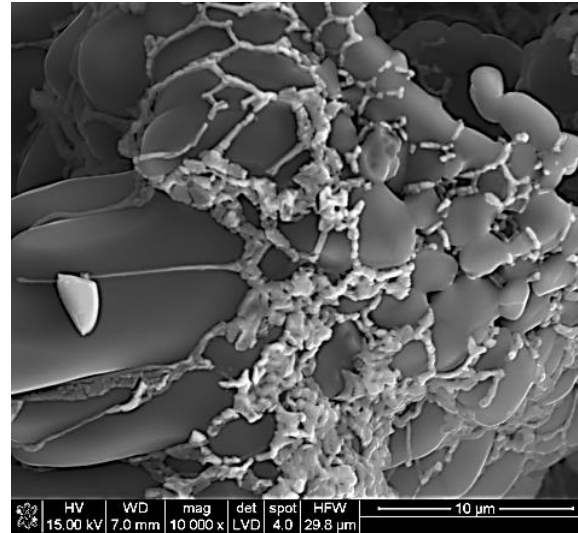
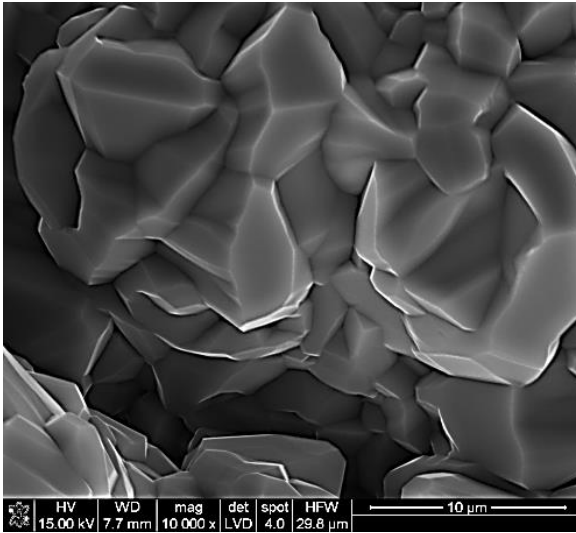
Synthesis of Aluminium nitride by SHS



- 1) Heating supply
- 2) Mixture of (Al+ AlN)
- 3) Powdery bed
- 4) Heat insulator

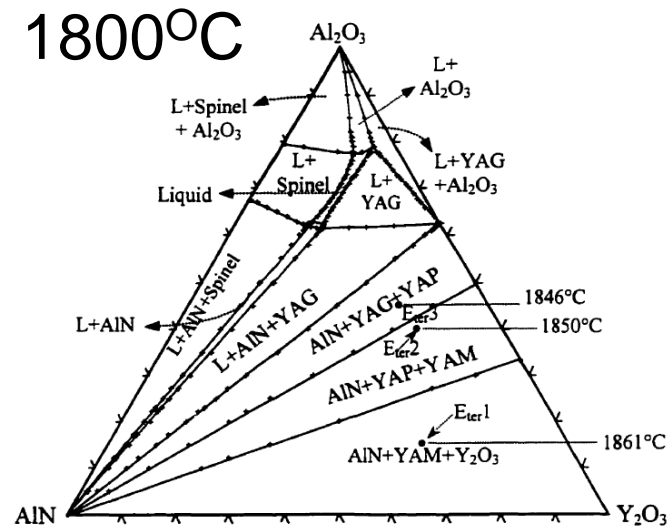
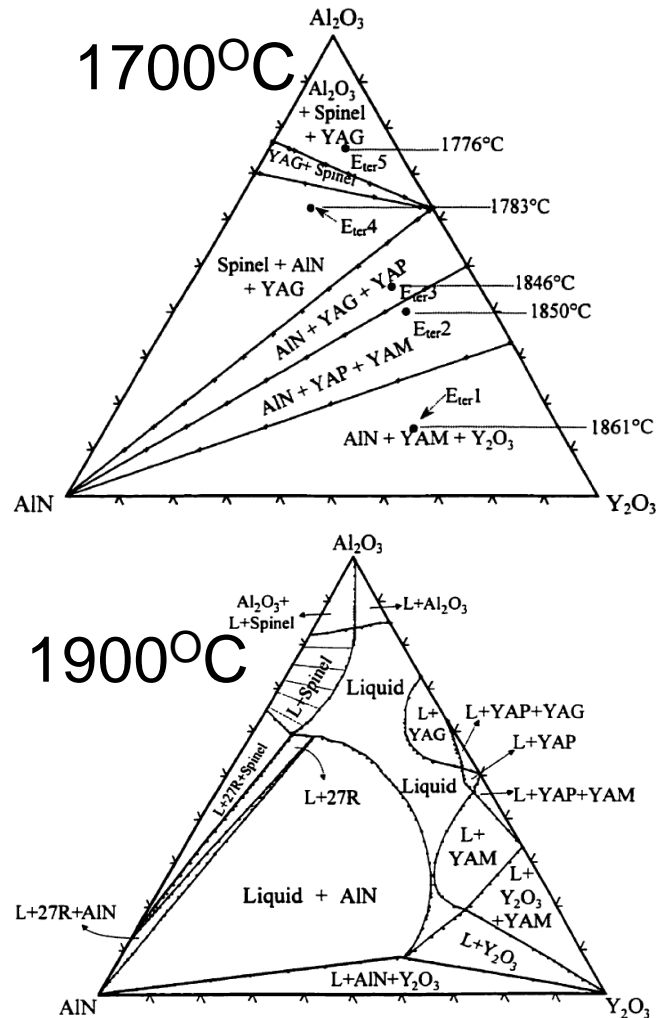


Scheme of SHS equipment for SHS combustion



Morphology of SHS derived AlN powders:

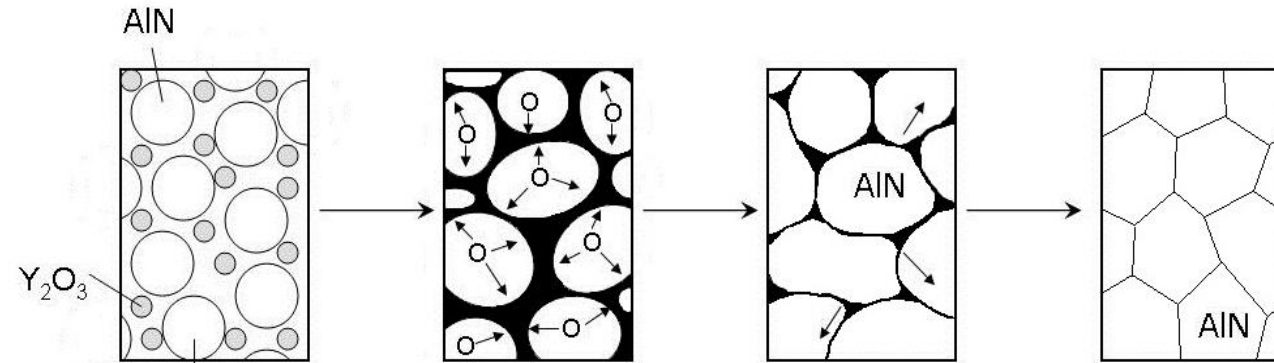
- a) Pure AlN
- b) AlN + 6% Y_2O_3 ;
- c) AlN + 8% Y_2O_3 ;
- d) AlN + 10% Y_2O_3 ;



Phase Diagram of AlN-Y₂O₃-Al₂O₃ system

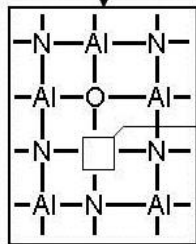
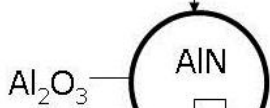
Mamoun Medraj, PHASE EQUILIBRIA IN THE AlN-Al₂O₃-Y₂O₃ SYSTEM - UTILITY IN AlN PROCESSING, McGill University Montreal Canada, PhD, 2001

Sintering of AlN with addition of Y_2O_3



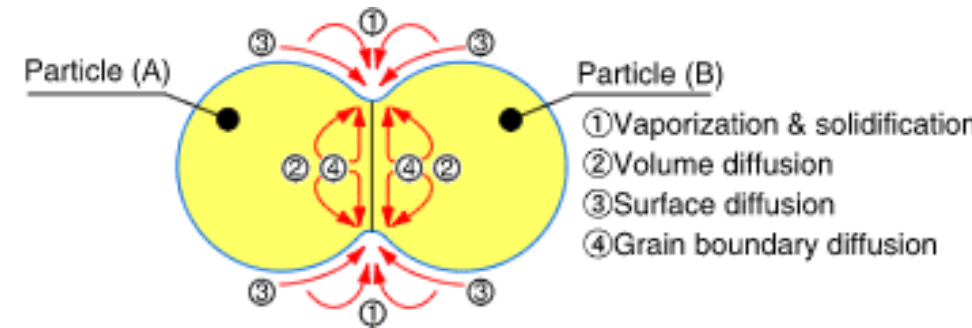
$$[V_{\text{ścisk.}}] = \exp\left(-\frac{E_v + \sigma\Omega_v}{kT}\right) = [V_0] \exp\left(-\frac{\sigma\Omega_v}{kT}\right) \quad \longrightarrow \quad \text{compressive stress}$$

$$[V_{\text{rozcz.}}] = \exp\left(-\frac{E_v - \sigma\Omega_v}{kT}\right) = [V_0] \exp\left(\frac{\sigma\Omega_v}{kT}\right) \quad \longrightarrow \quad \text{tensile stress}$$



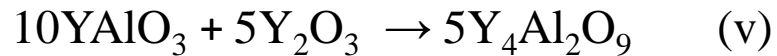
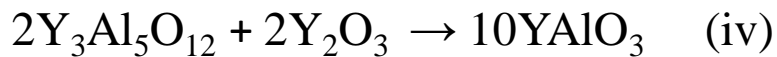
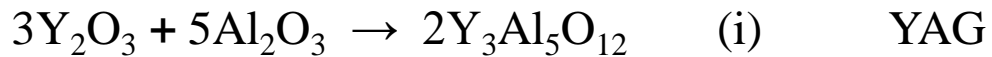
Wakancja glinowa

Vacancies Al



Stress at the grain boundary is not enough for purification of AlN grains during sintering

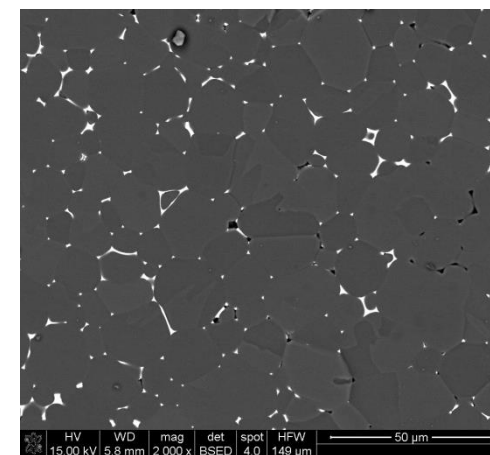
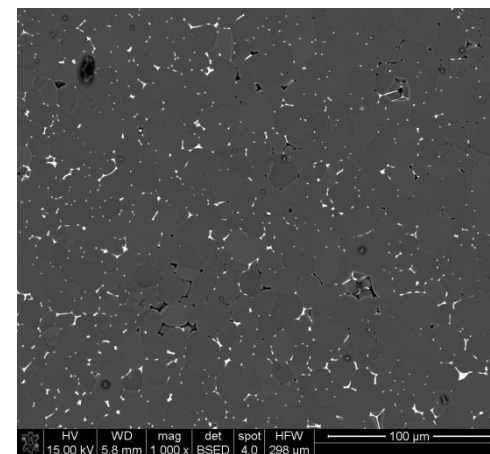
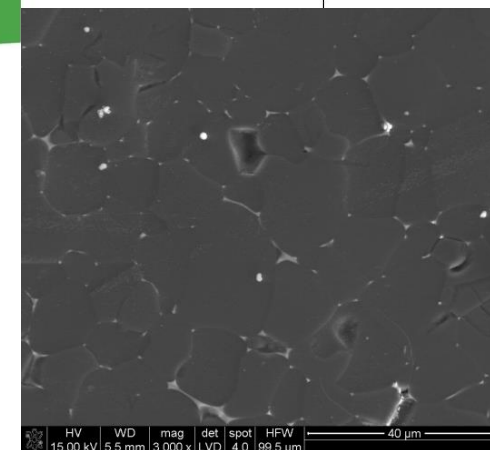
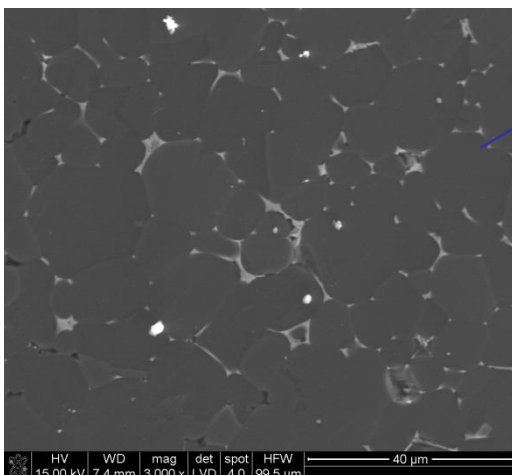
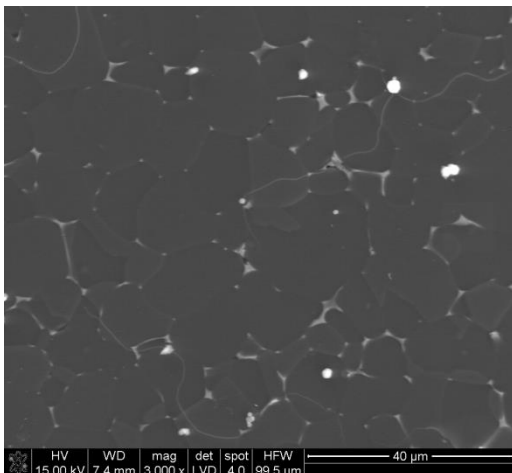
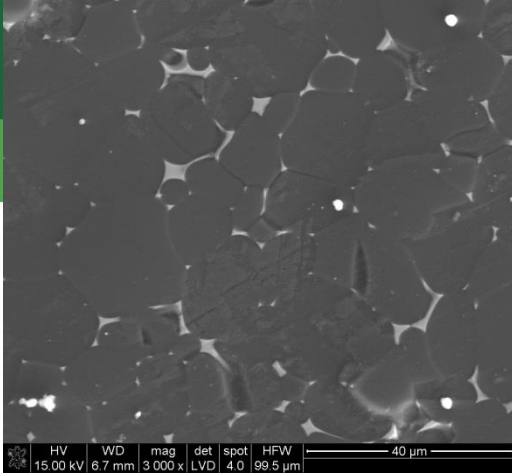
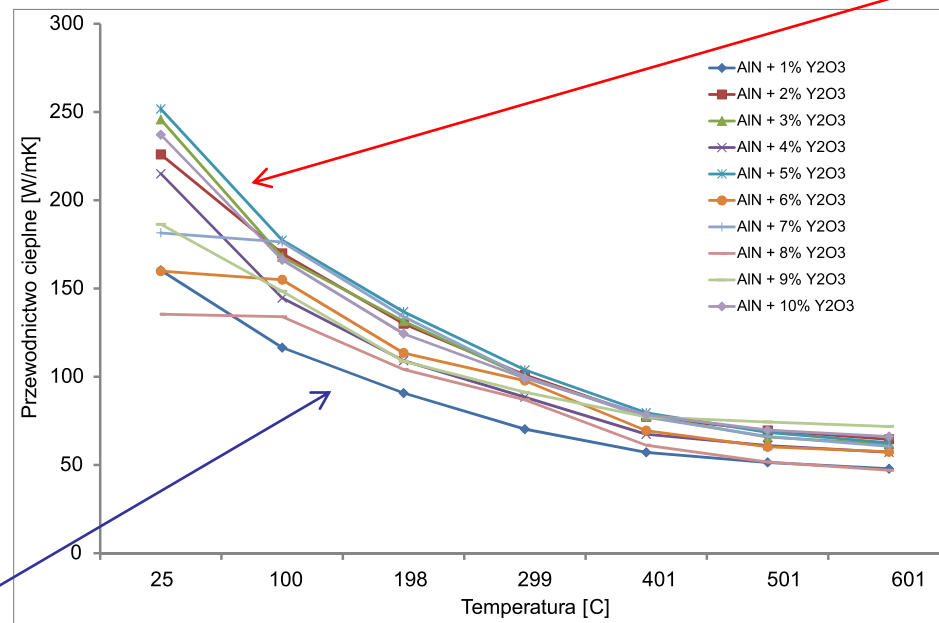
Grain boundary reactions during AlN sintering



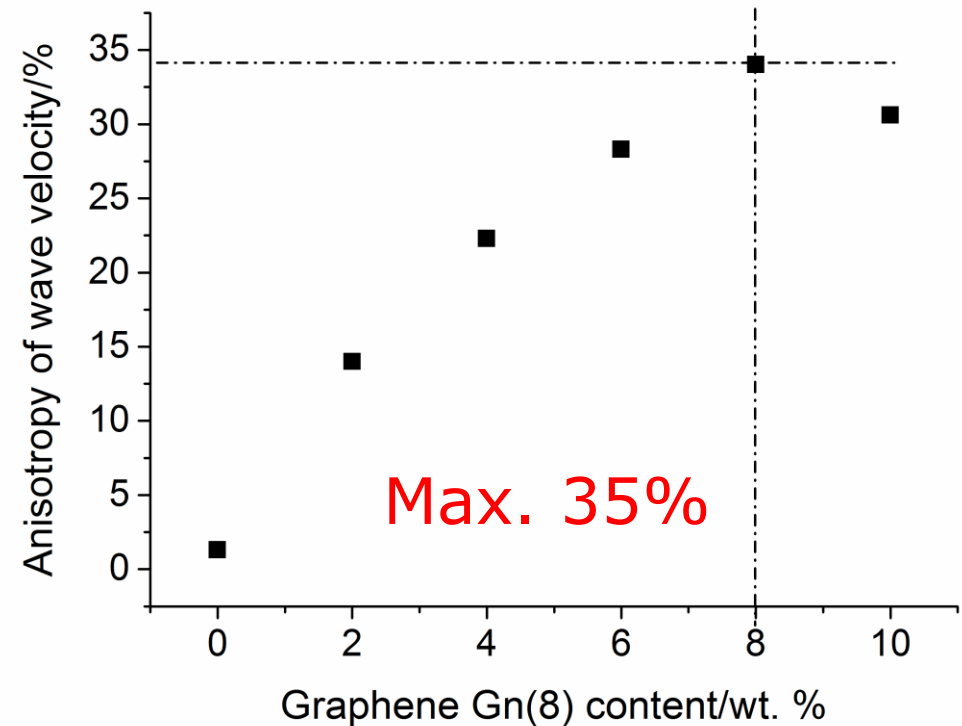
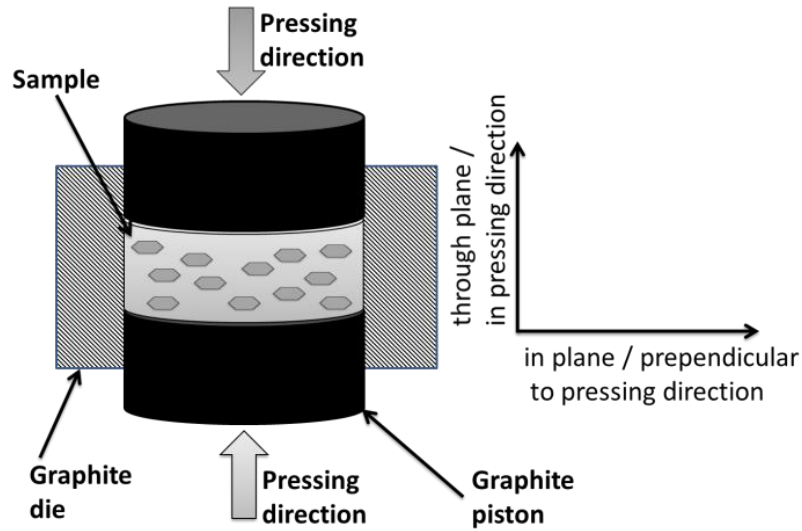
| Phase | Formula | Ratio Y_2O_3 - Al_2O_3 | Crystallographic system | λ [W/mK]* |
|-------|--------------|-------------------------------|----------------------------|-------------------|
| YAG | $Y_3Al_5O_9$ | 3:5 | Regular | 2,5 |
| YAP | $YAlO_3$ | 1:1 | Orthorhombic, hexagonal | 4,3 |
| YAM | $Y_4Al_2O_9$ | 2:1 | Monoclinic | 7,4 |

*T.B. Jackson, A.V. Virkar, K.L. More, R.B. Dinwiddie, and R.A. Cutler, J. Am. Ceram. Soc. 80, 1421 (1997).

Pressureless sintering 1900°C 1,0 hour

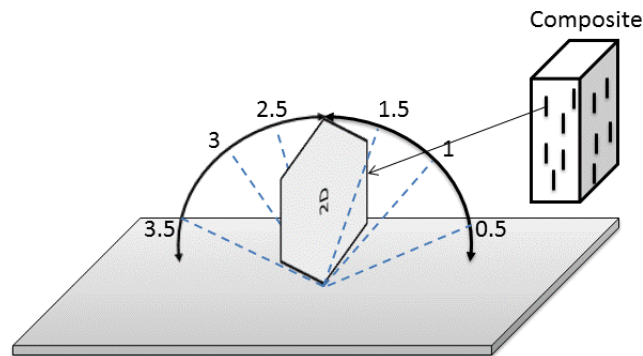


Anisotropy of AlN/GPLs composites (ultrasonic measurements)

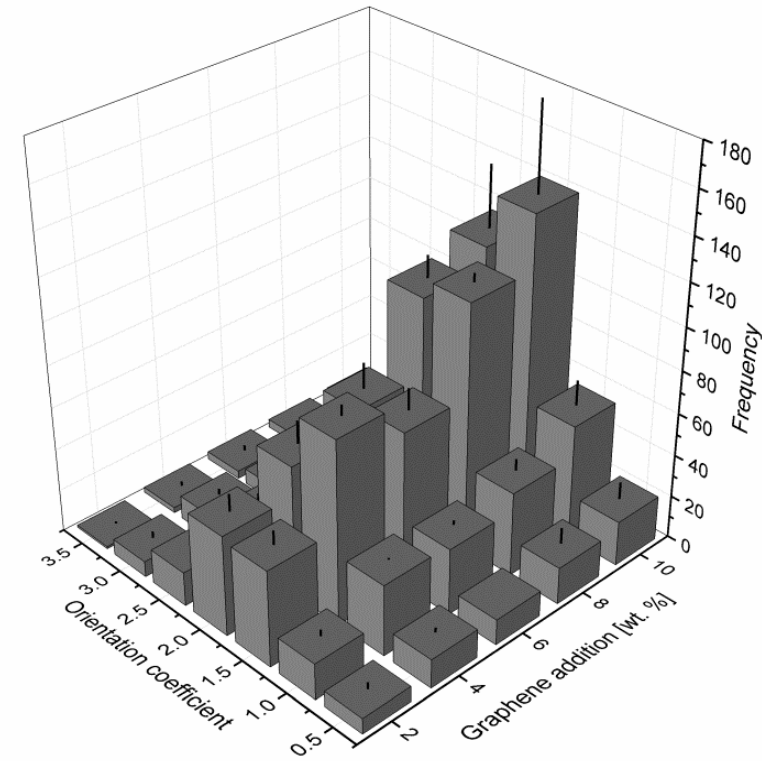


Anisotropy of AlN/GPLs composites (Computer-aided microstructure analysis)

| Material | The maximum equivalent diameter d_{2max} [μm] | The average equivalent diameter d_{2mean} [μm] | The average diameter D [μm] |
|-------------------|--|---|--|
| AlN | 10.90 | 4.49 | 5.88 |
| AlN + 2 wt% GPLs | 11.74 | 5.03 | 6.53 |
| AlN + 4 wt% GPLs | 6.00 | 2.30 | 3.01 |
| AlN + 6 wt% GPLs | 5.97 | 2.07 | 2.66 |
| AlN + 8 wt% GPLs | 6.55 | 2.37 | 2.94 |
| AlN + 10 wt% GPLs | 6.88 | 2.38 | 2.96 |

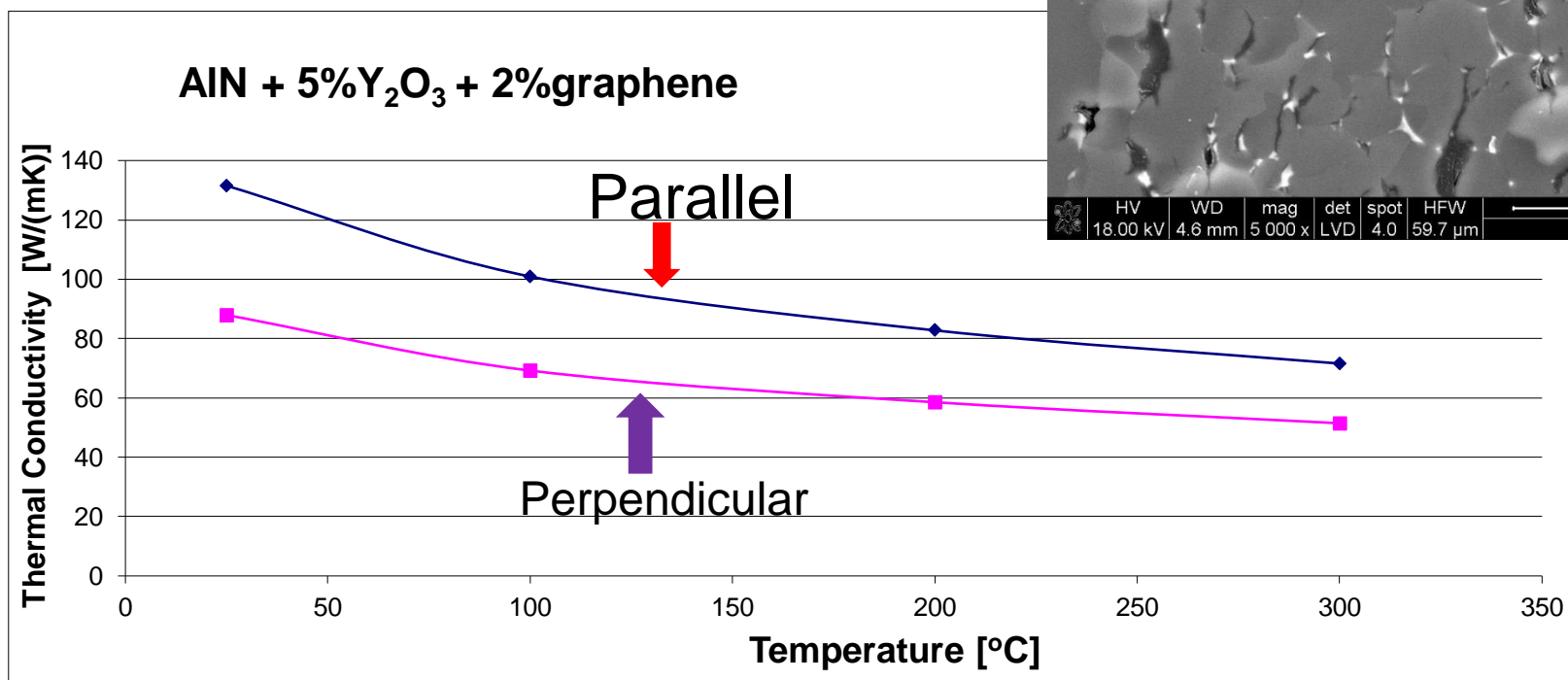
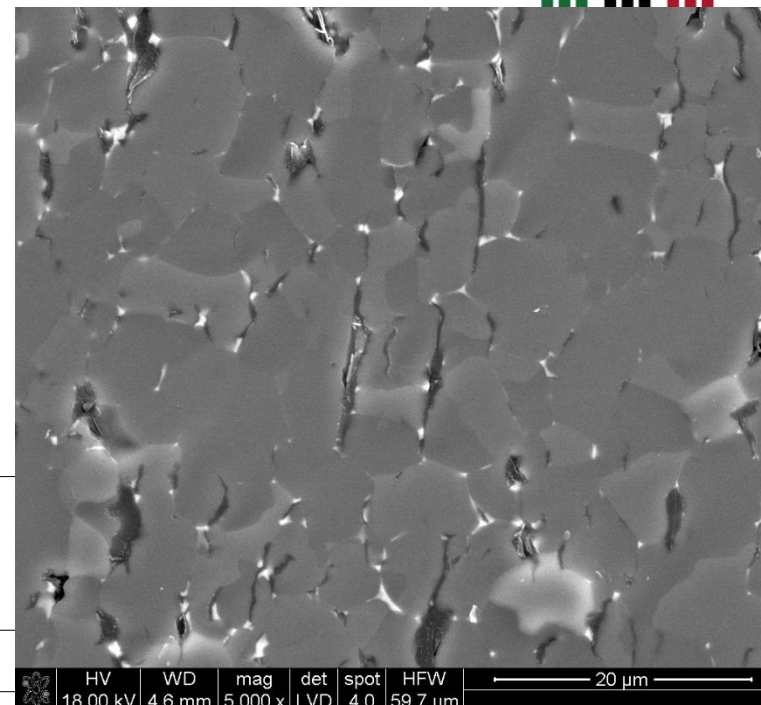


Orientation coefficient



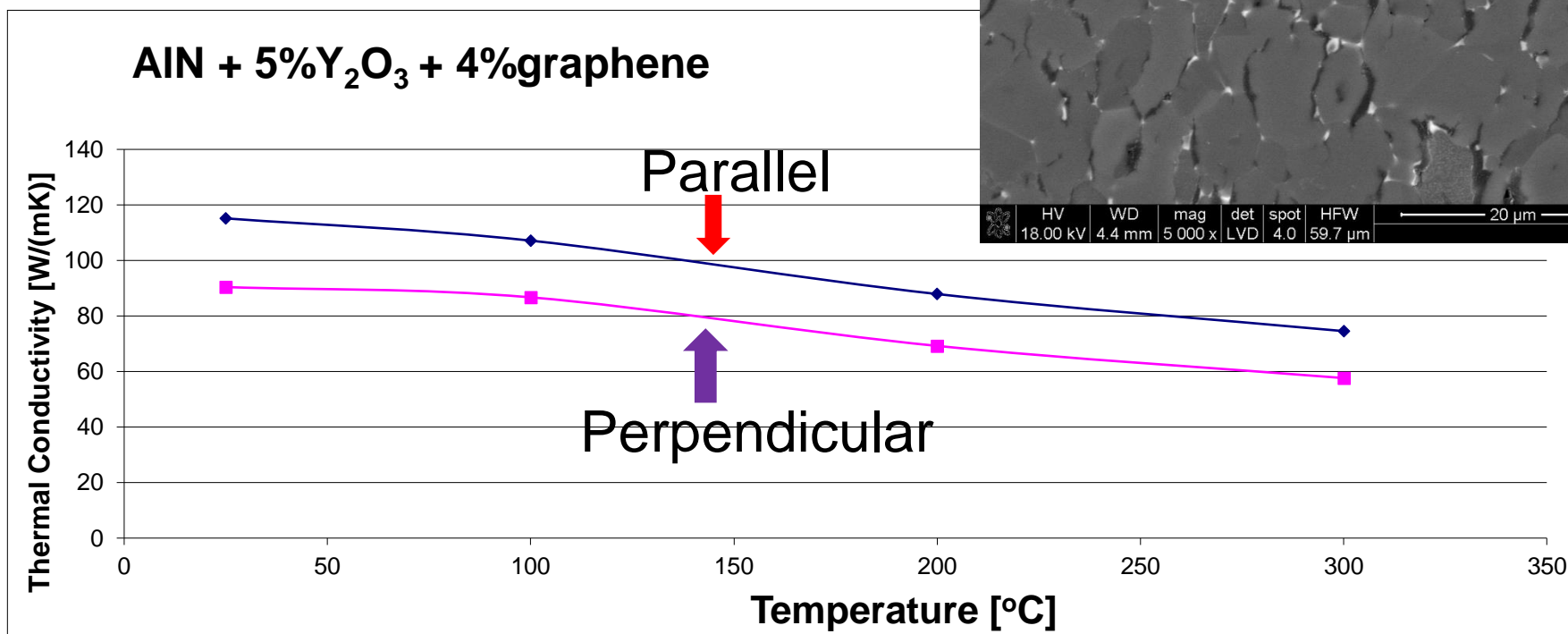
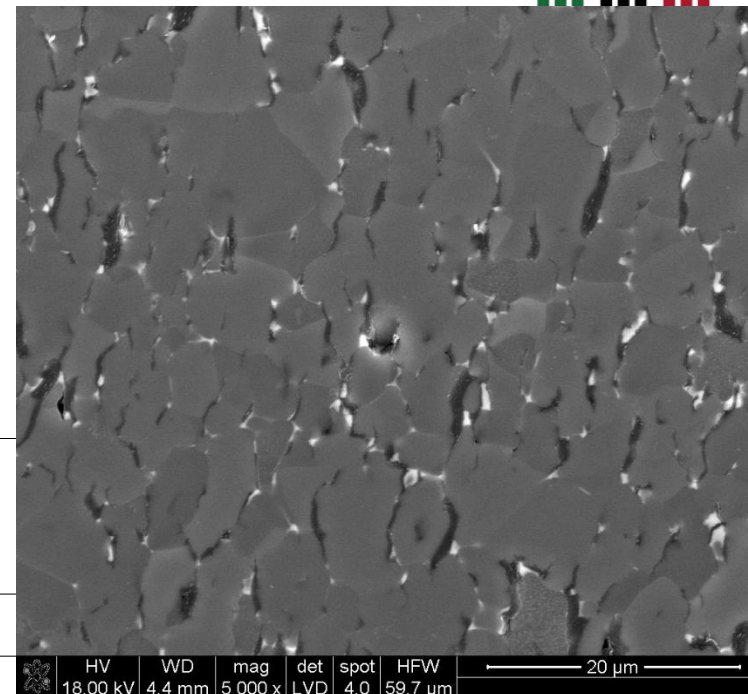


Thermal conductive anisotropy of AlN-graphen nanocomposites



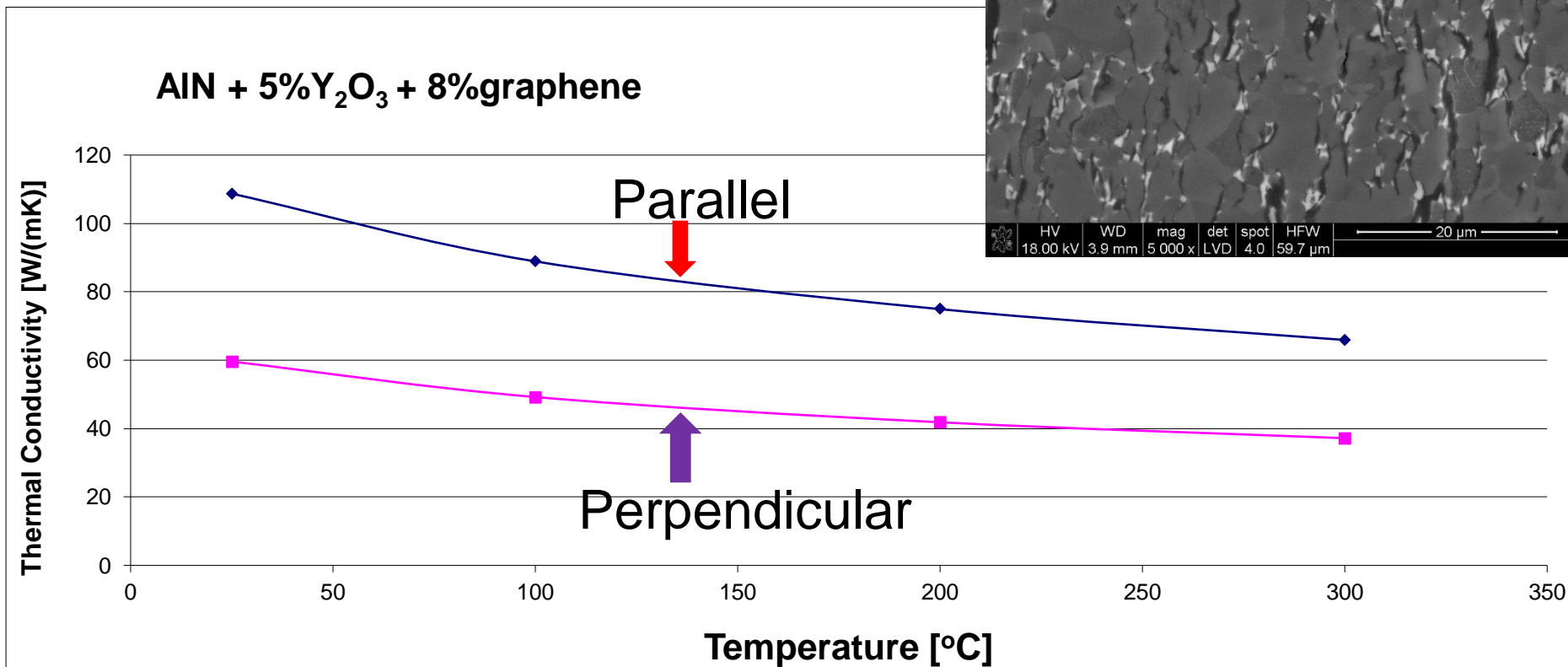
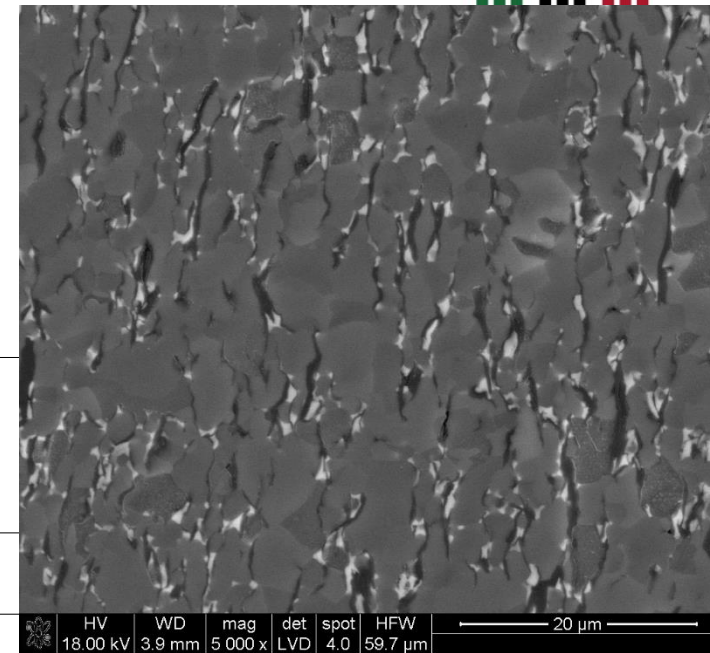


Thermal conductive anisotropy of AlN-graphen nanocomposites



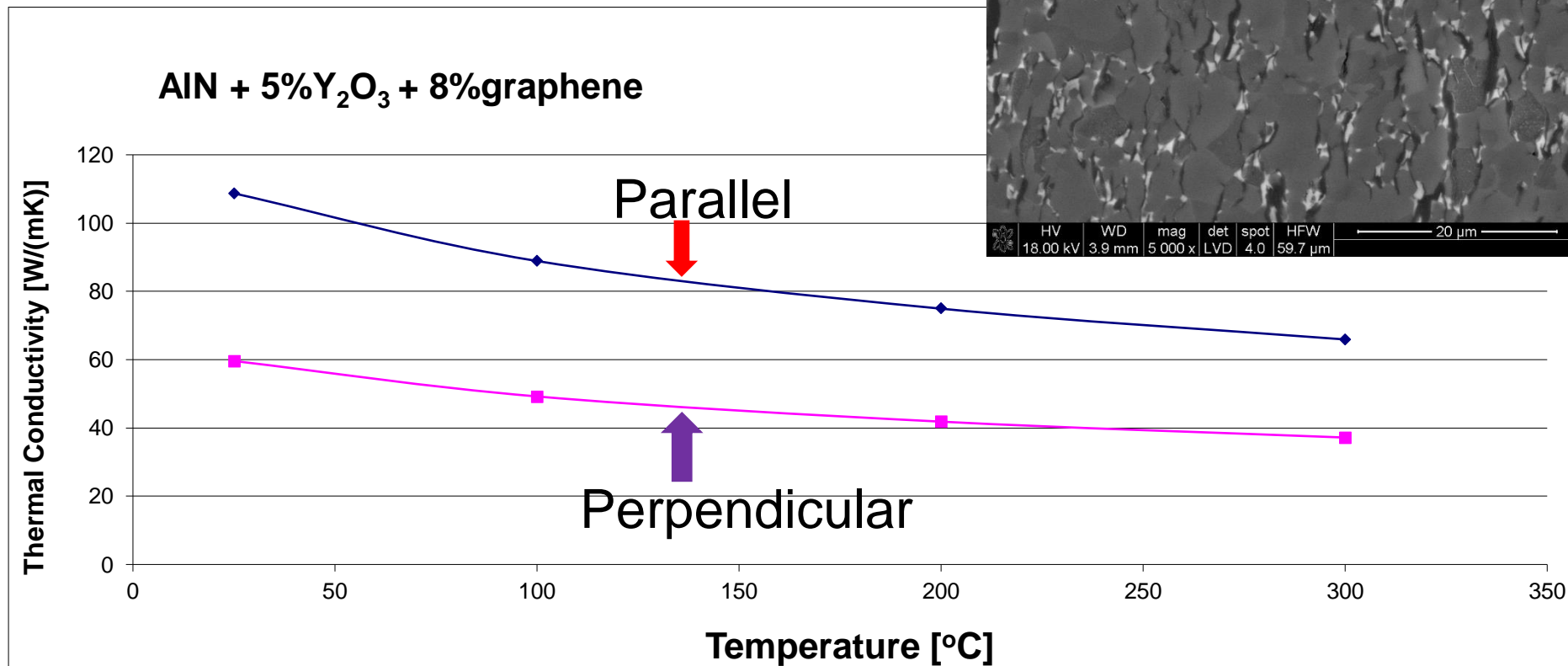


Thermal conductive anisotropy of AlN-graphen nanocomposites





Thermal conductive anisotropy of AlN-graphen nanocomposites

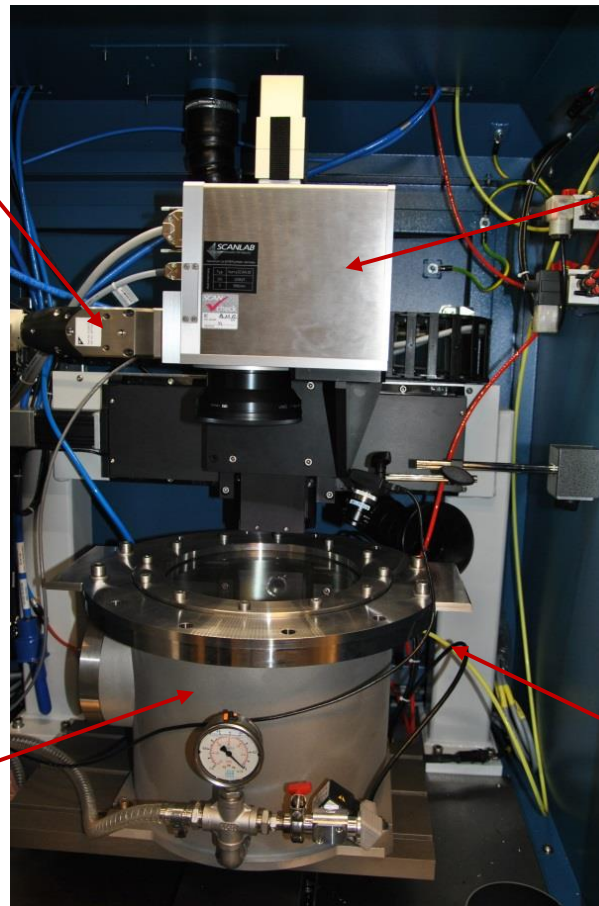


The influence of graphite/graphene additions on Fiber Laser Scanner Processing

Laser beam supply

Two kinds of fibre laser supply: 200 (10 μm accuracy) and 2000kW (50 μm accuracy)

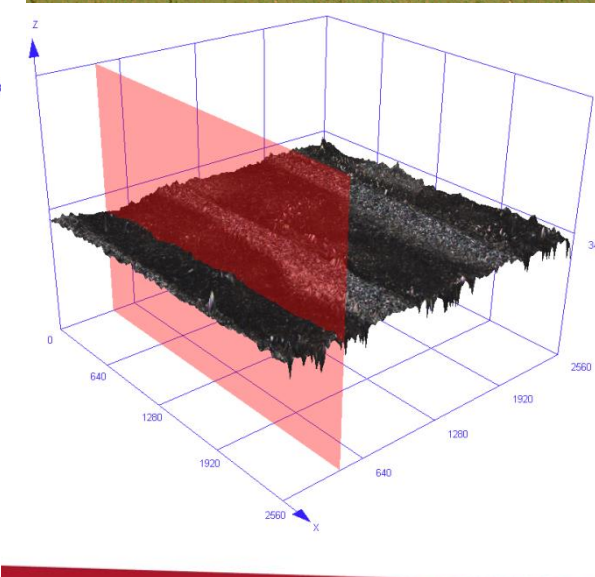
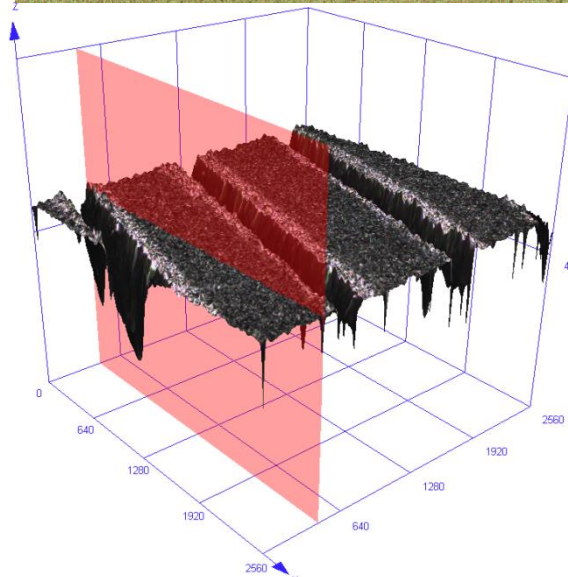
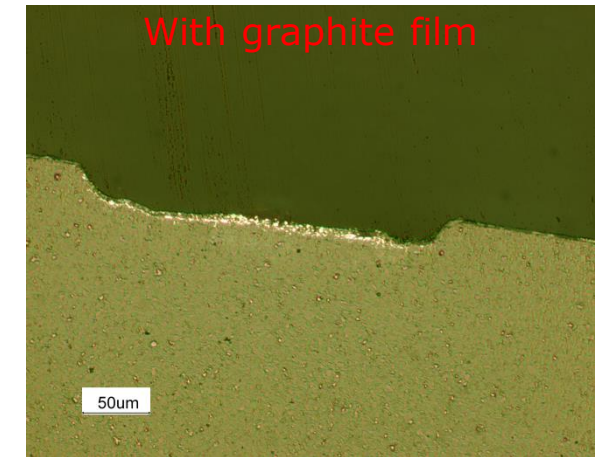
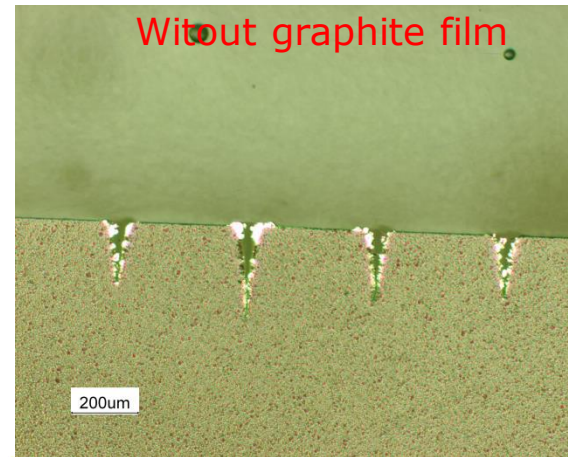
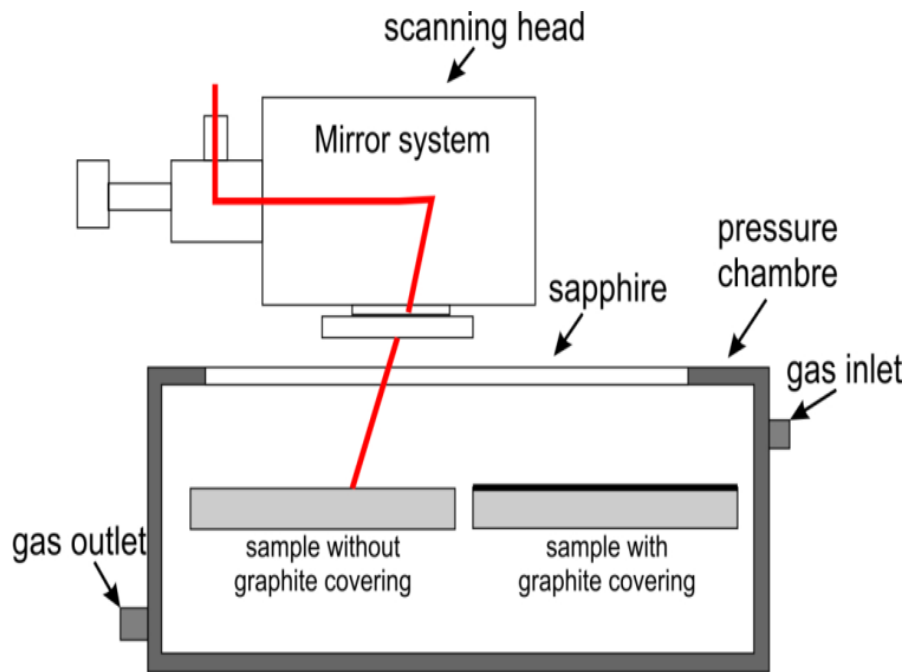
Specially designed pressure chamber with possibility of temperature control

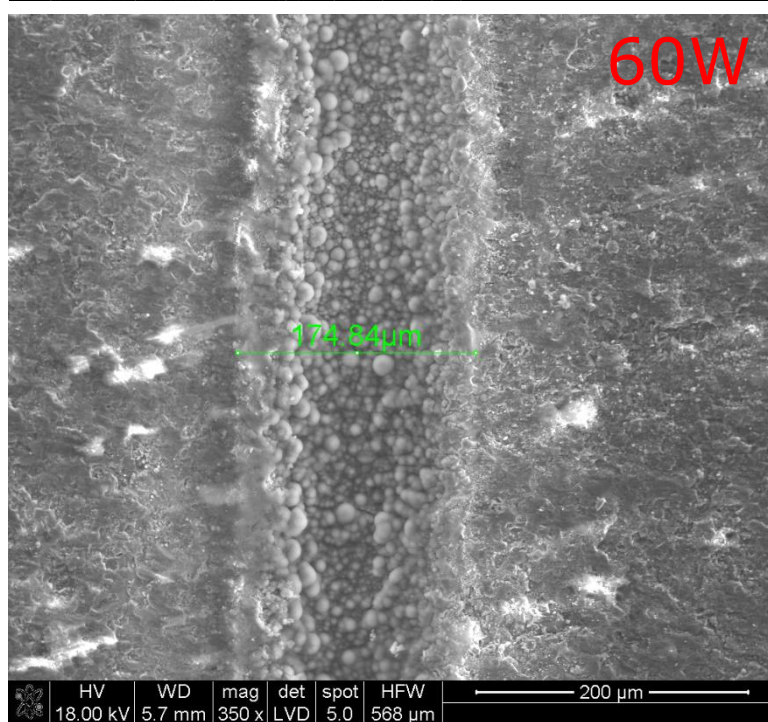
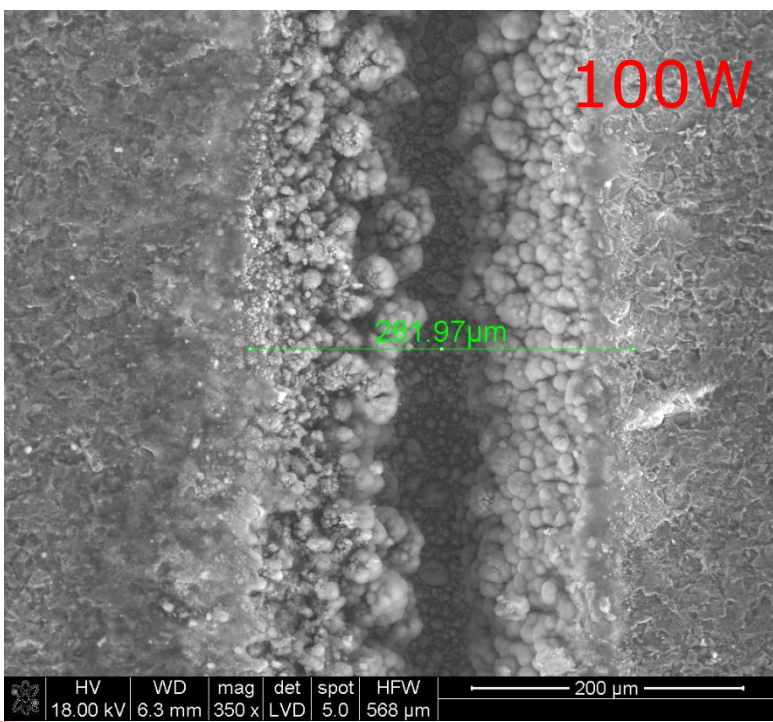
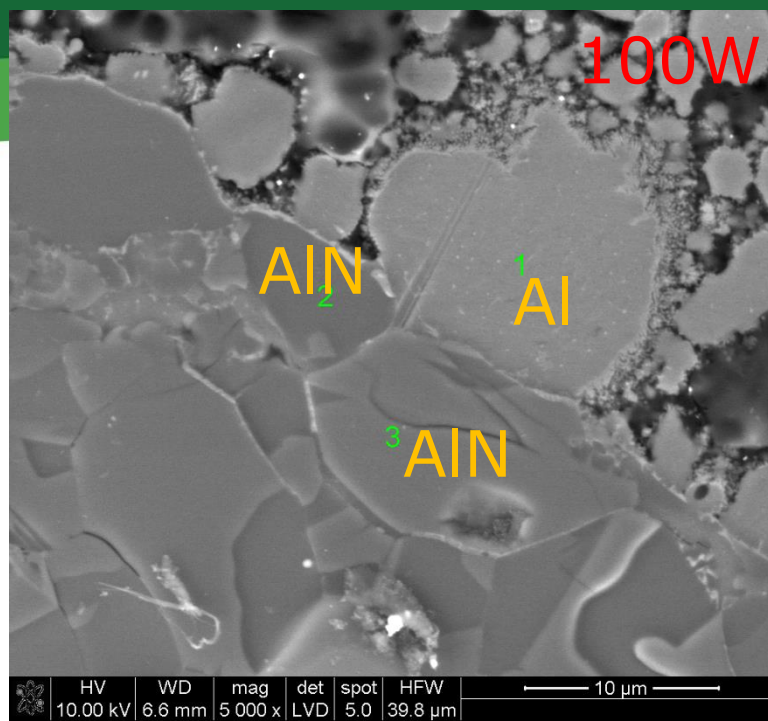
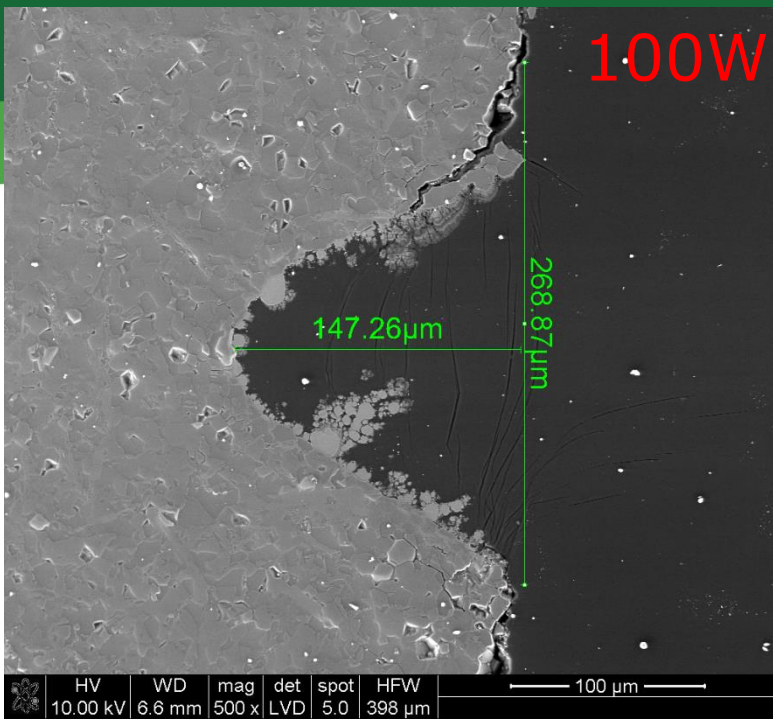


Scanner head

Nitrogen gas 5 bars pressure

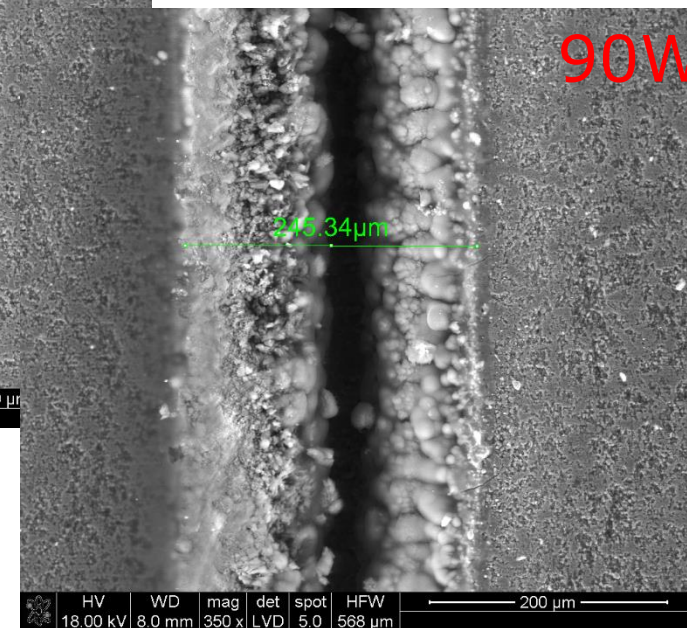
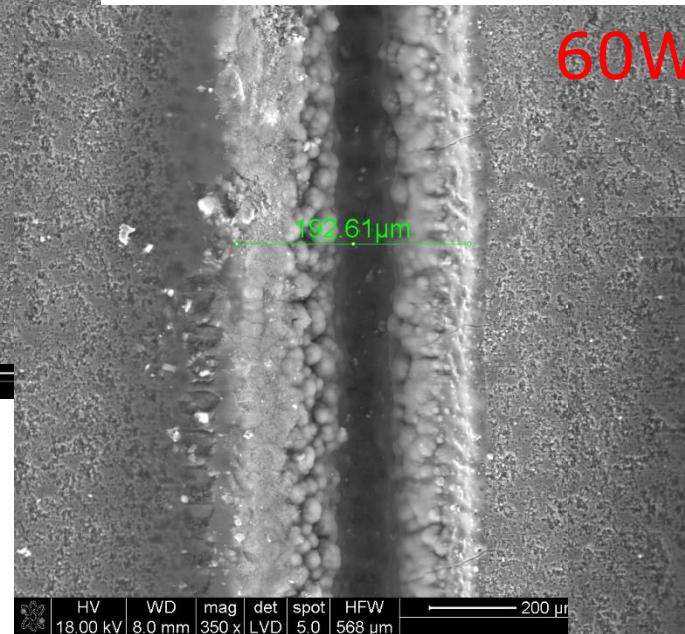
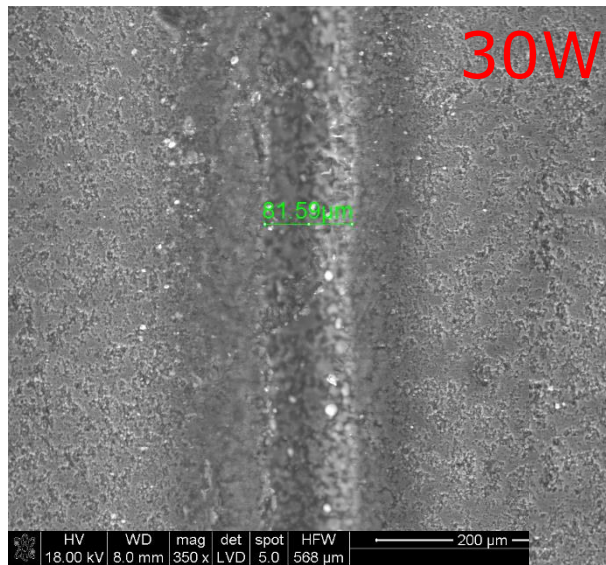
Fiber Laser Scanner AlN processing



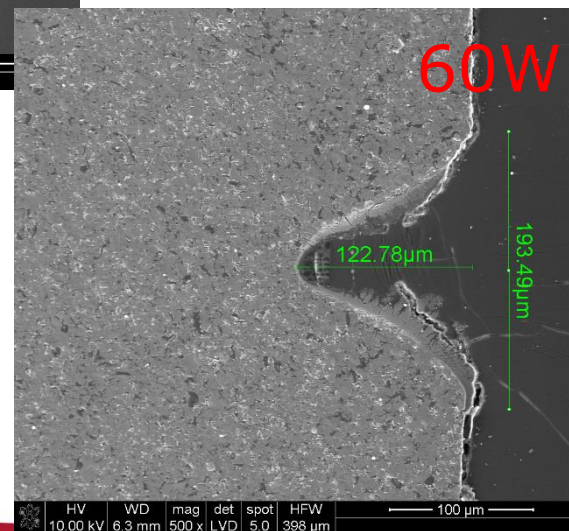
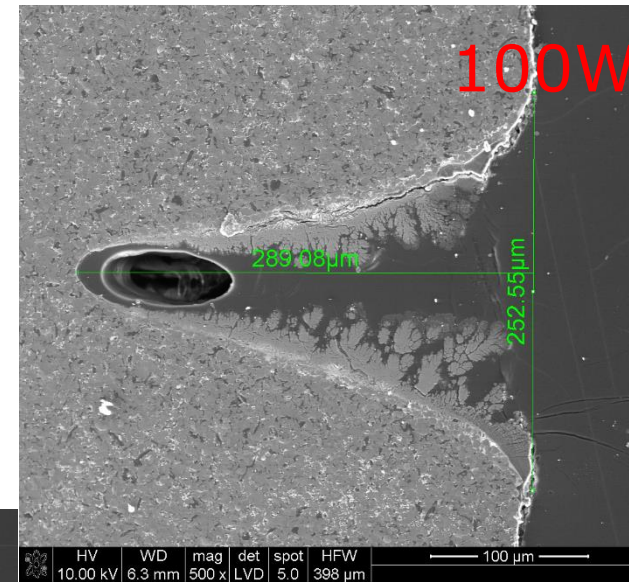
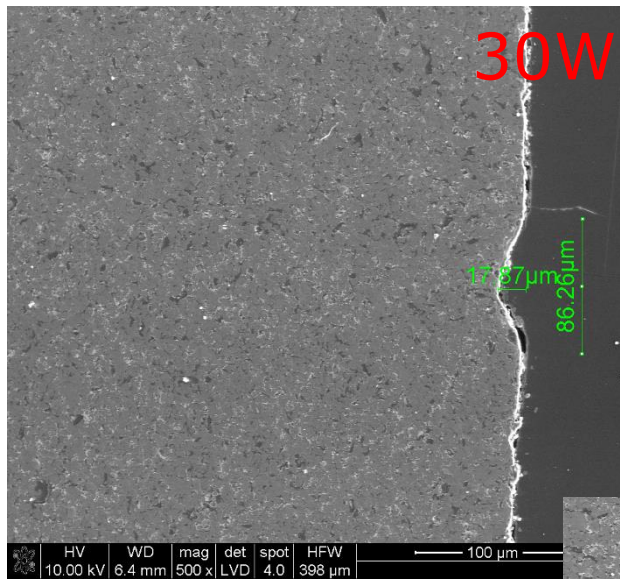


AIN laser shpaing

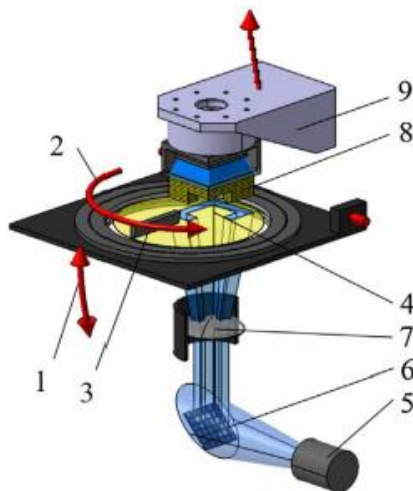
Laser processing of AlN + 10 wt% GPLs composites



Laser processing of AlN + 10 wt% GPLs composites



Additive manufacturing of AlN by UV-resin AlN suspension

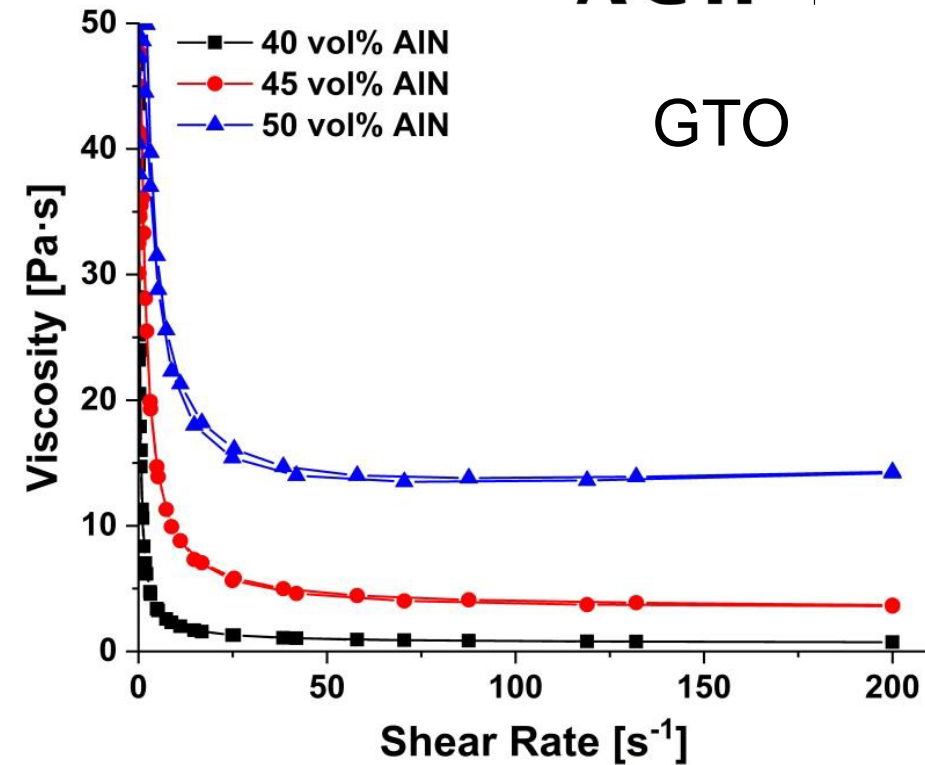
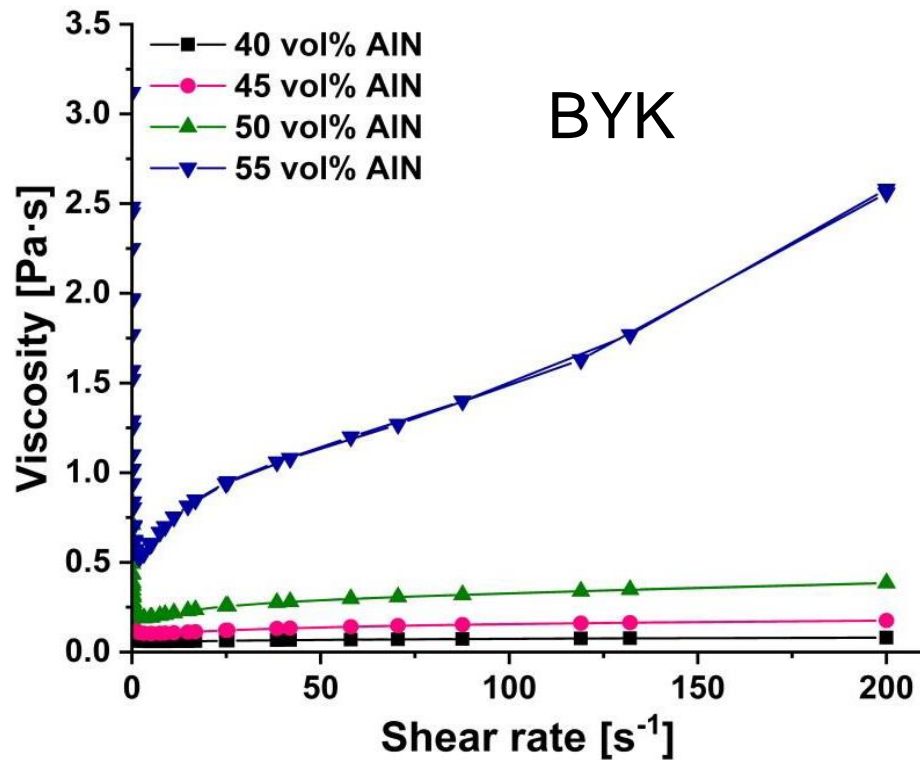


1. Tilting mechanism,
2. Rotating mechanism,
3. Coating blade,
4. Exposed slurry,
5. LED light source,
6. DMD chip,
7. Optics,
8. Green part,
9. Z-stage

CeraFab 7500 3D printer from Lithoz
(Austria)



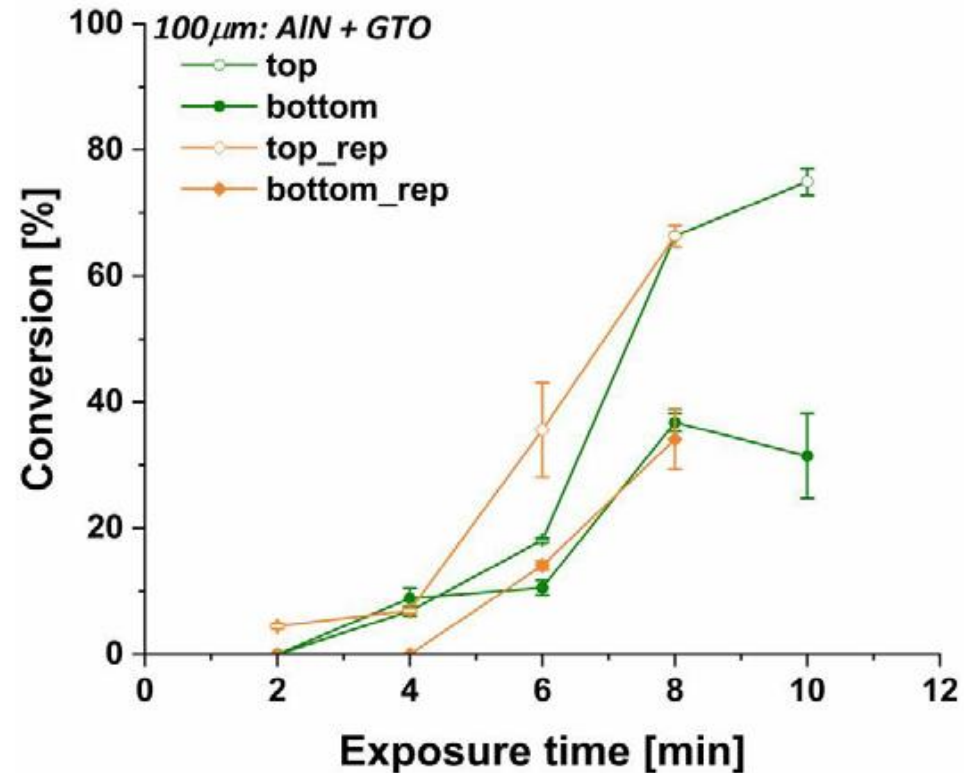
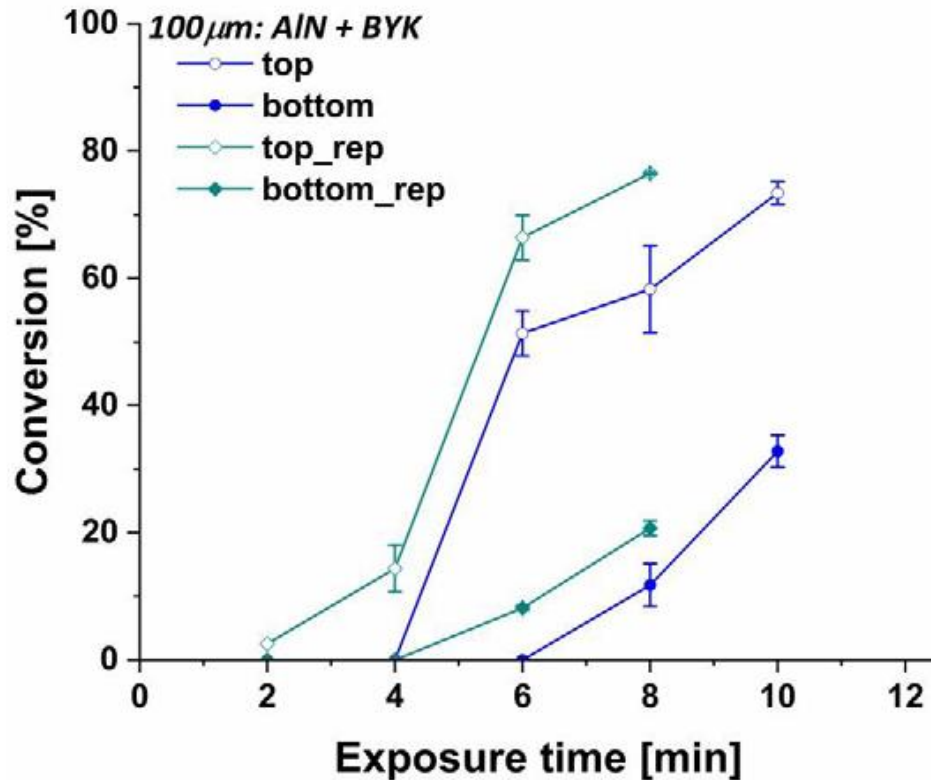
Influence of different dispersing agent on rheological behaviour of AlN slurries



Two different dispersing agents were examined; BYK-W 9010 from Additives & Instruments (Germany) and glyceryl trioleate (GTO) from Sigma Aldrich (Switzerland)

P. Ożóg, D. Kata, T. Graule, Tape casting of UV-curable aluminium nitride-based slurries, *Ceram. Int.* 44 (2018) 22800–22807.
doi:10.1016/j.ceramint.2018.09.071.

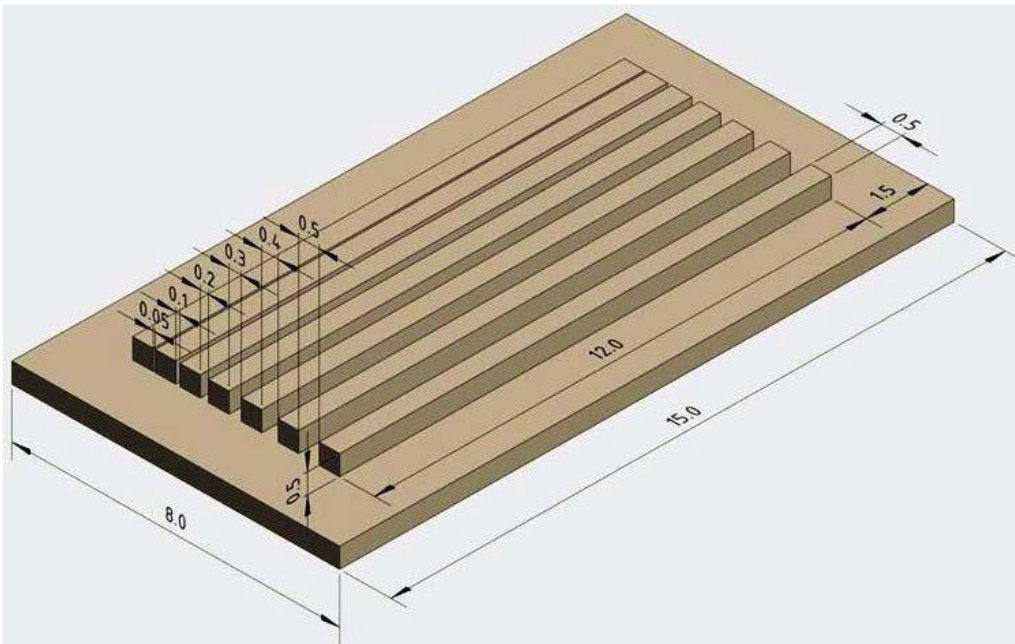
Conversion degree of AlN slurries influenced by exposure time



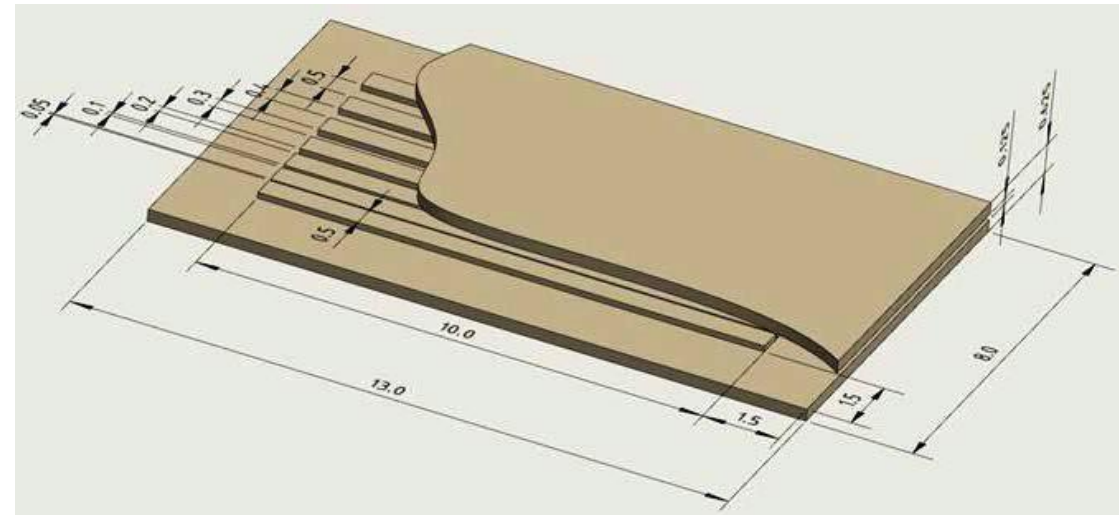
P. Ożóg, D. Kata, T. Graule, Tape casting of UV-curable aluminium nitride-based slurries, *Ceram. Int.* 44 (2018) 22800–22807. doi:10.1016/j.ceramint.2018.09.071.

Microheat exchanger test designs

a)

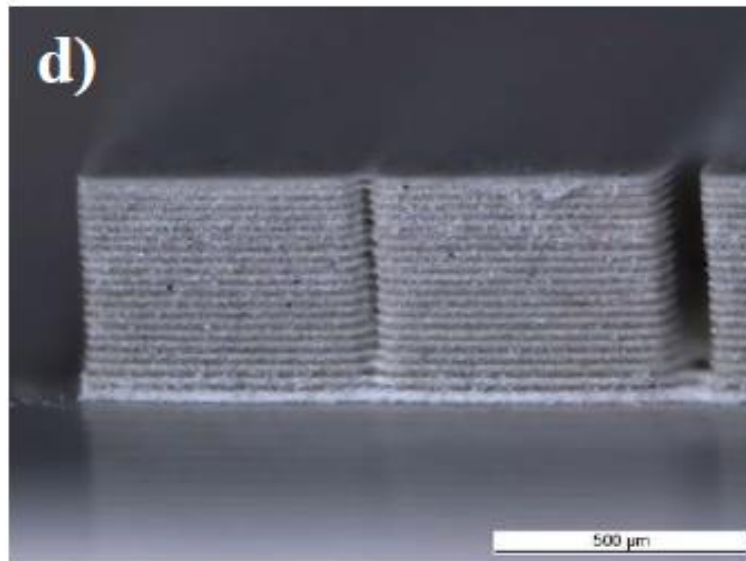
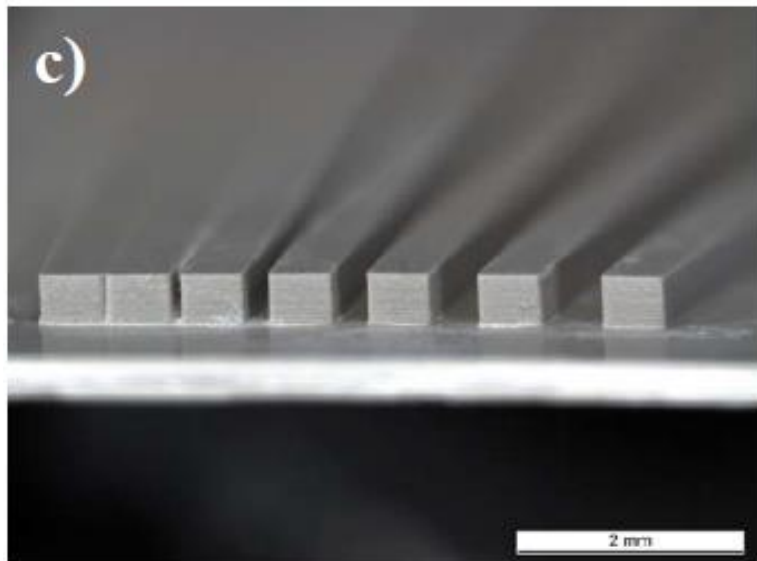
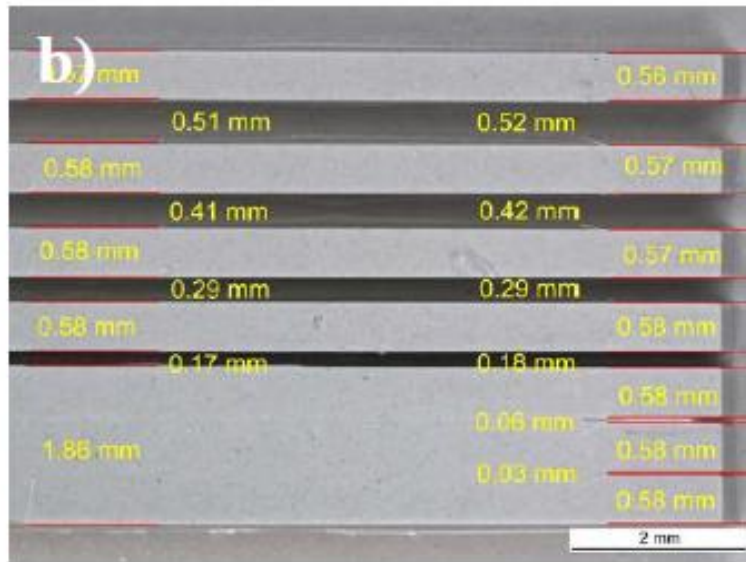
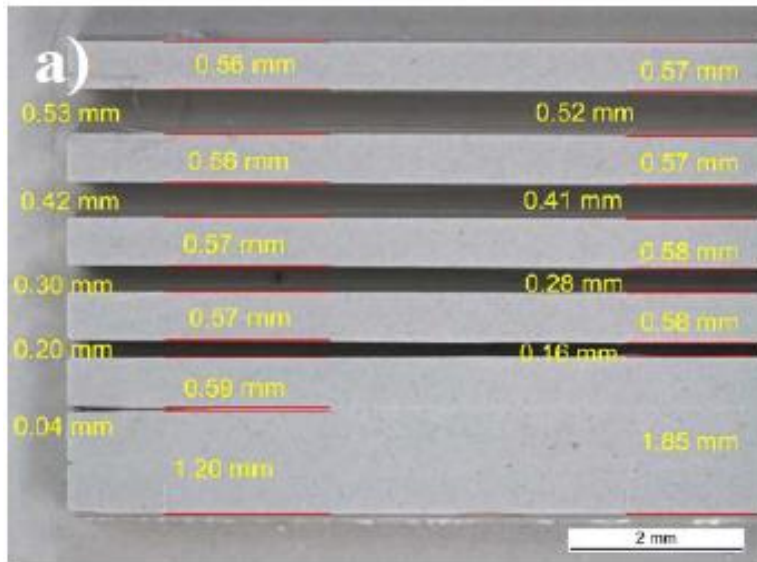


b)

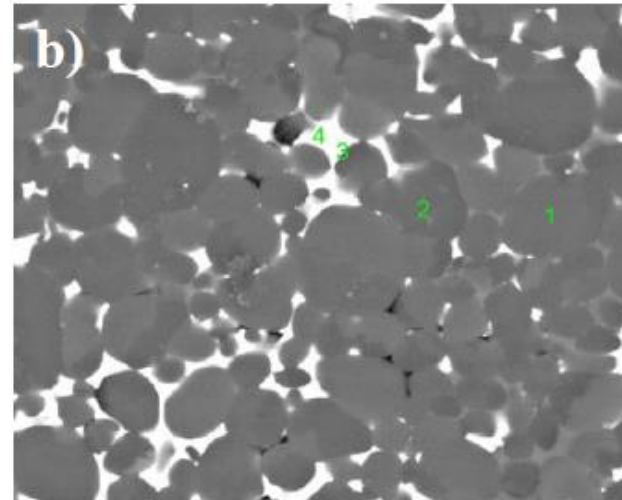
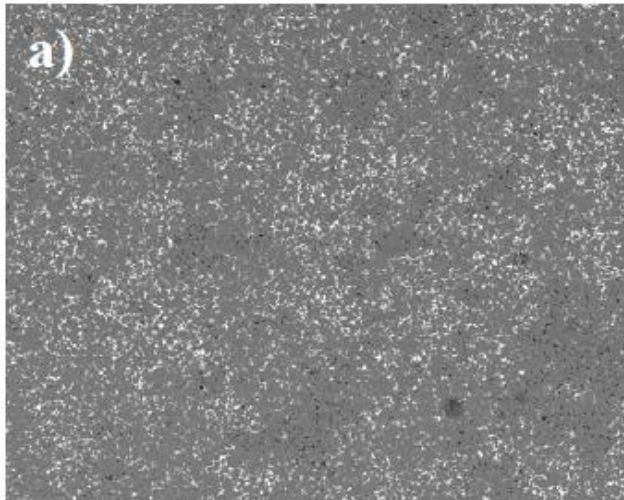


Microheat exchanger test designs: a) plate with channels (PCH);
b) plate with channels and cover (PCHC) [drawing prepared by Roland Bätchold, Empa]

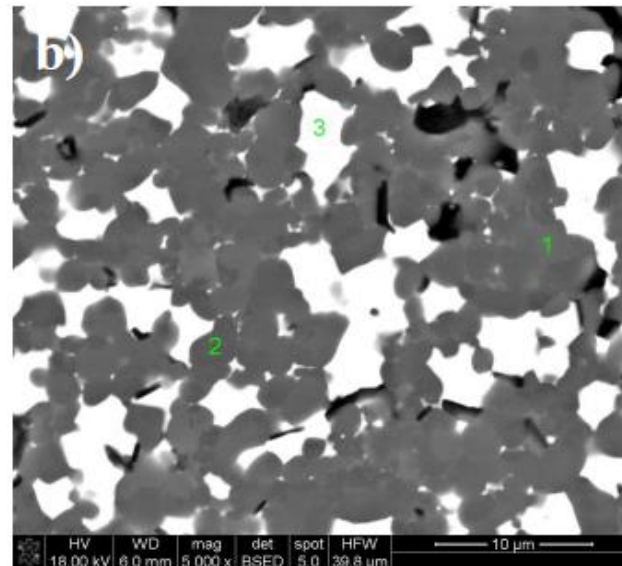
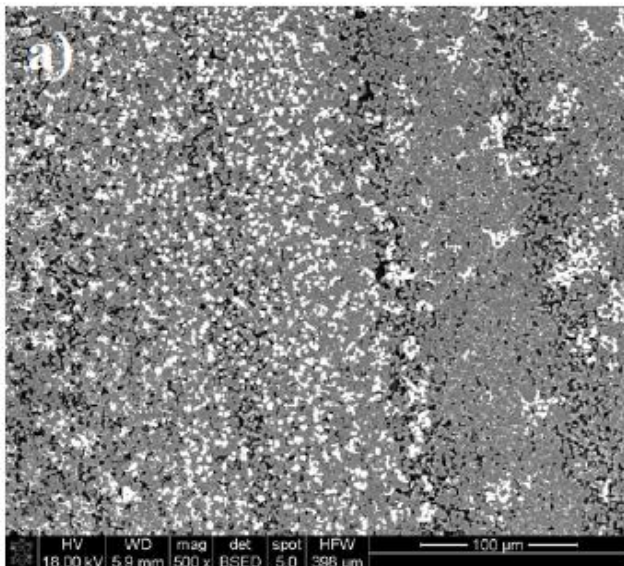
AlN microheat exchanger additive manufactured



AlN microstructure examination



AlN microstructure prepared by conventional pressureless sintering



AlN microstructure prepared by additive manufacturing

Rapid high-energy ceramics processes (RHEP)

Using of high-energy sources for local synthesis or consolidation of powders
(economic processing)



Rapid local heating of materials
(SHS, Laser Manufacturing, Laser Sintering, Spark Plasma Sintering etc.)



Rapid temperature growth and, after the process, very rapid cooling



Rapid physicochemical phenomena during reaction, sintering etc.



Possibility to prepared unique compounds



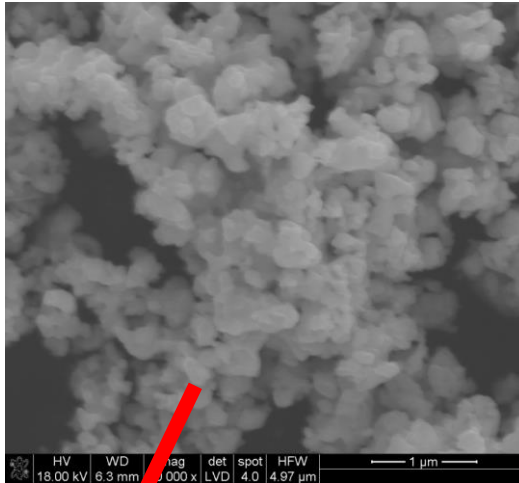
Examples:

1. Self-Propagating High-Temperature Synthesis (SHS),
2. Laser Manufacturing (LM)

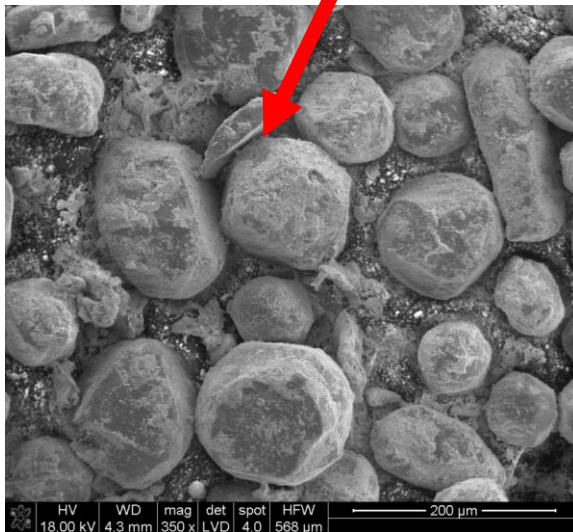
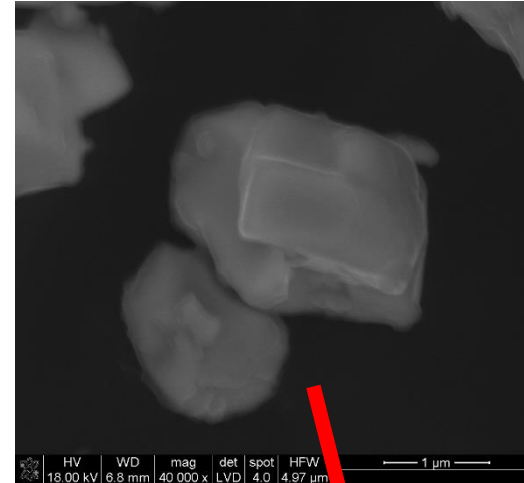
Inconel 625 – WC particles mixture preparation



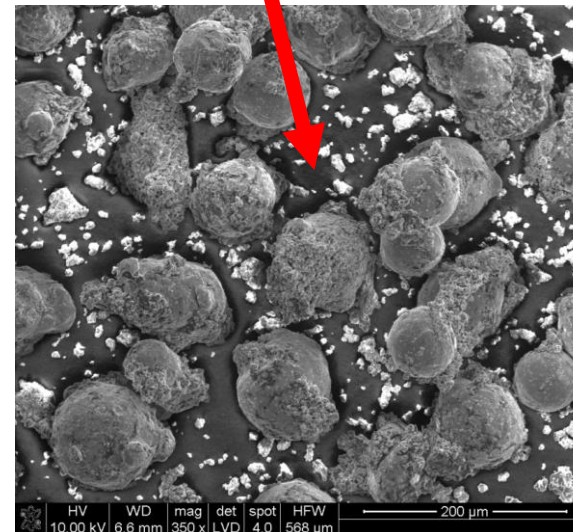
WC \approx 0.64 μ m



WC \approx 6.03 μ m



wet
homogenization
for 2 hours
including
0,5% resin

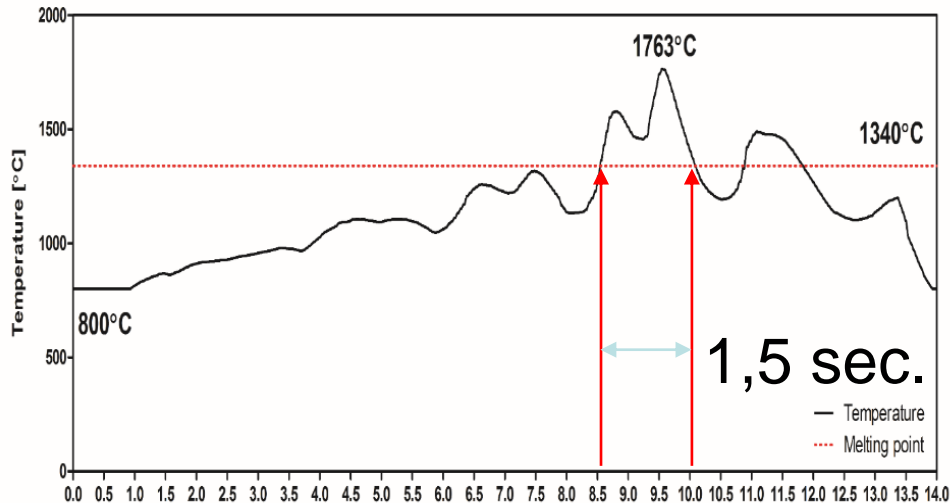


Inconel 625 + WC (0.64 μ m) mixture

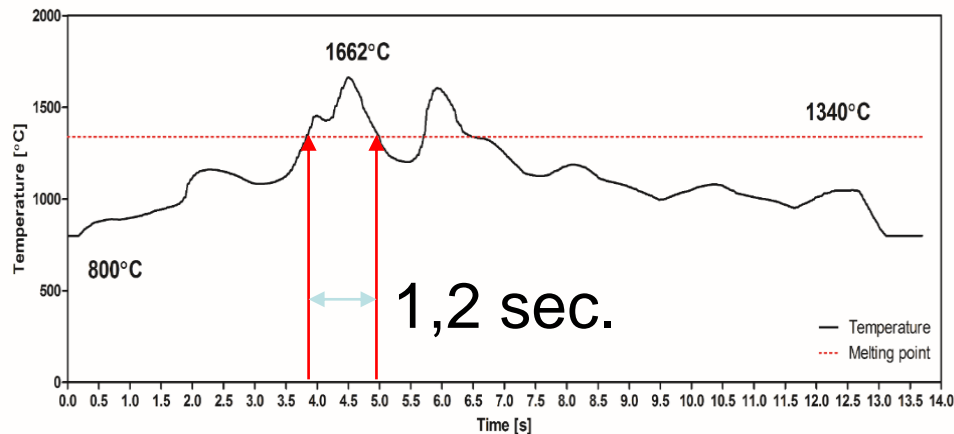
Inconel 625 + WC (6.03 μ m) mixture

3D manufacturing of Inconel – WC composites

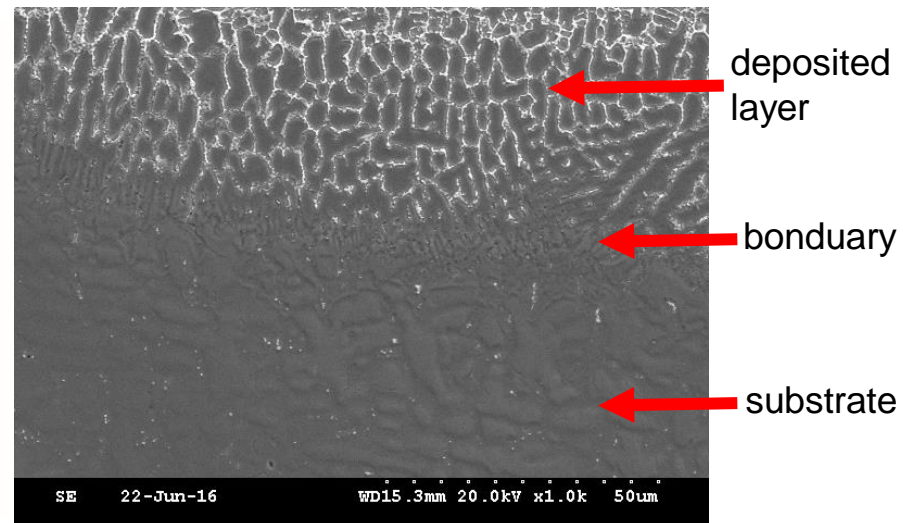
Inconel 625 - WC 0.63 μm



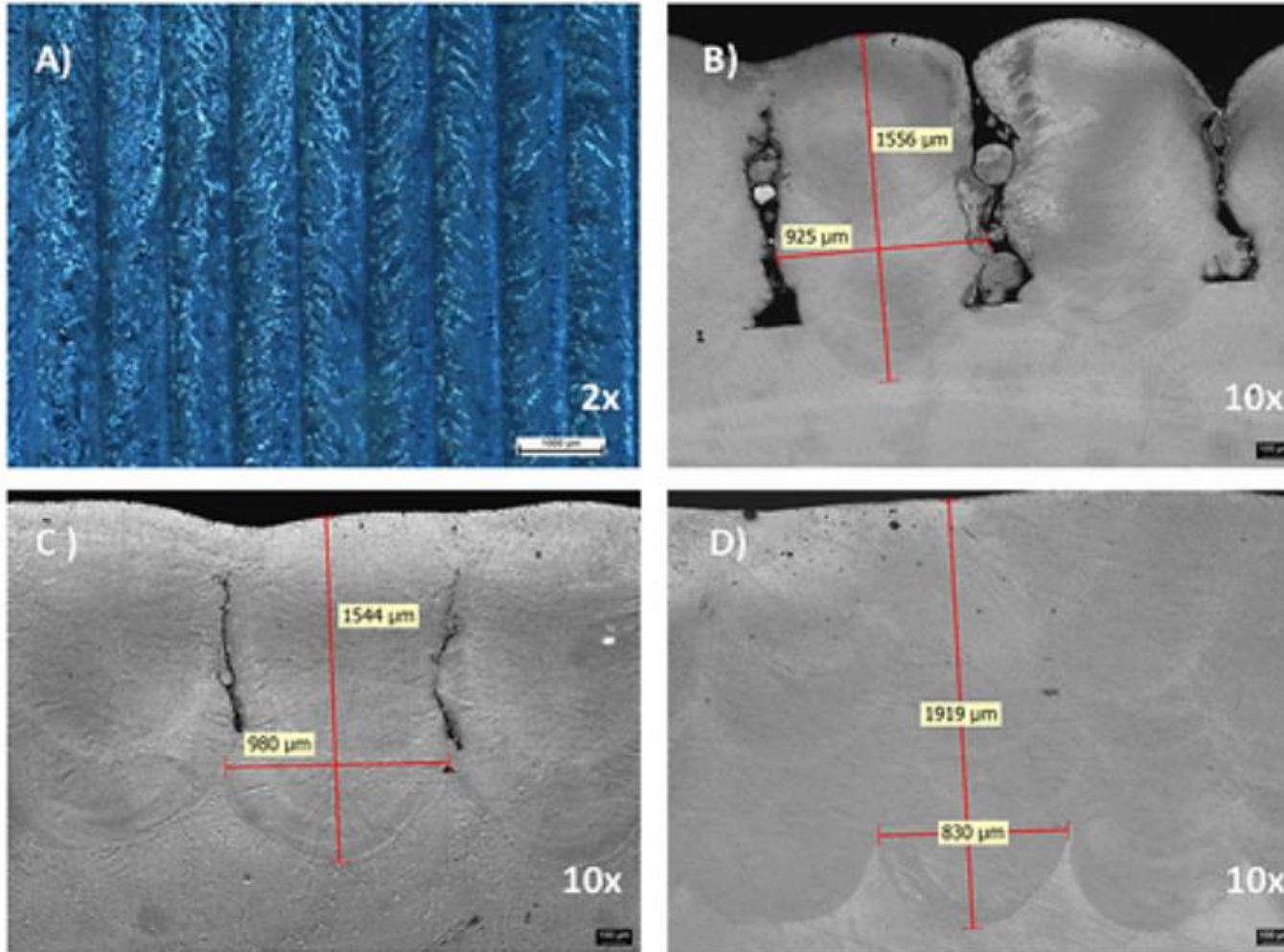
Inconel 625 - WC 6 μm



| Parameter | 1st attempt | 2nd attempt |
|-----------------------------------|-------------|-------------|
| Track length | 10 mm | 10 mm |
| Amount of consecutive tracks | 10 | 10 |
| Amount of sublayers | 6 | 6 |
| Laser beam diameter | 500 μm | 500 μm |
| Distance between center of tracks | 1 mm | 0.8 mm |
| Nominal laser power | 220 W | 320 W |
| Scanning velocity | 10 mm/s | 10 mm/s |



3D manufacturing of Inconel – WC composites

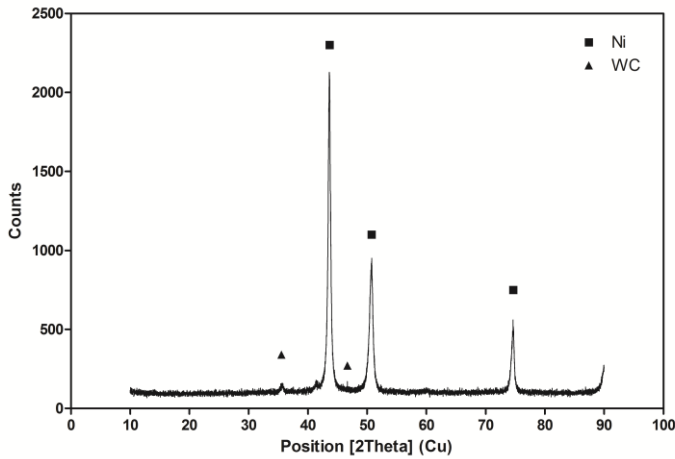


Microstructure appearance of laser shaped layers

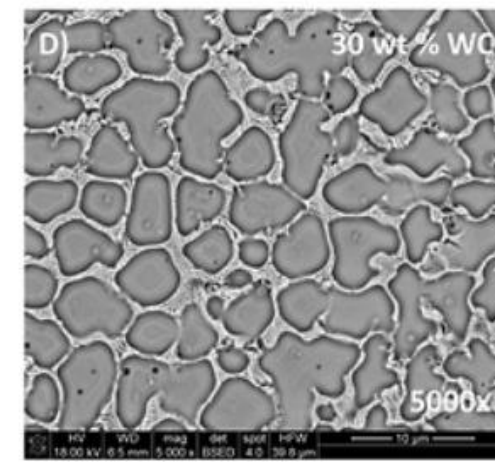
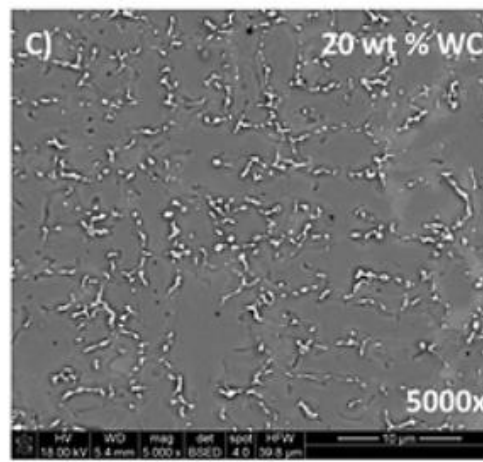
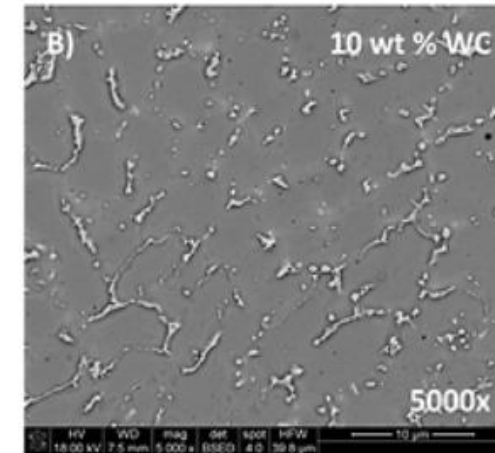
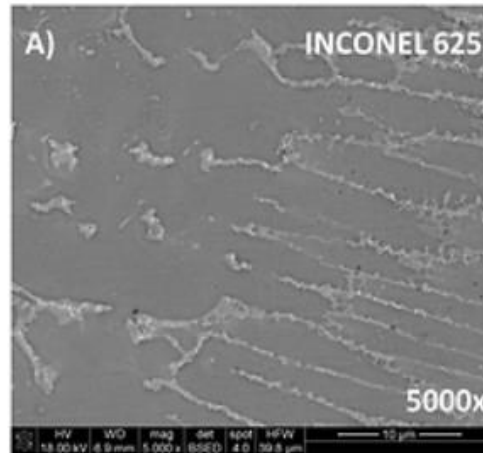
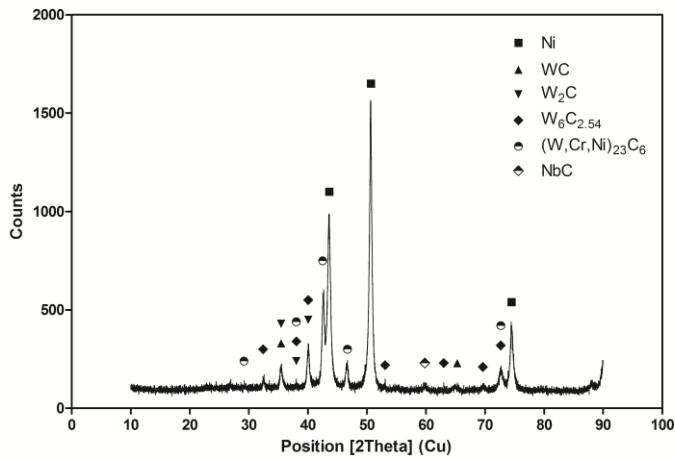
XRD and microstructure analysis of Inconel 625 - 10%, 20% and 30% WC additions



Inconel 625 - 20 wt % WC

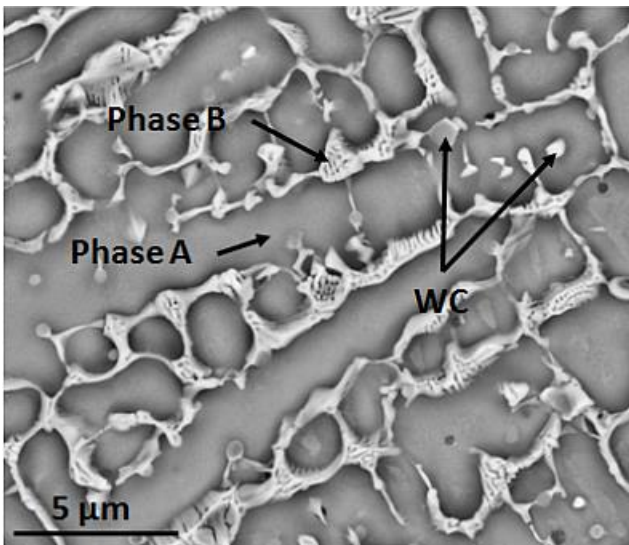
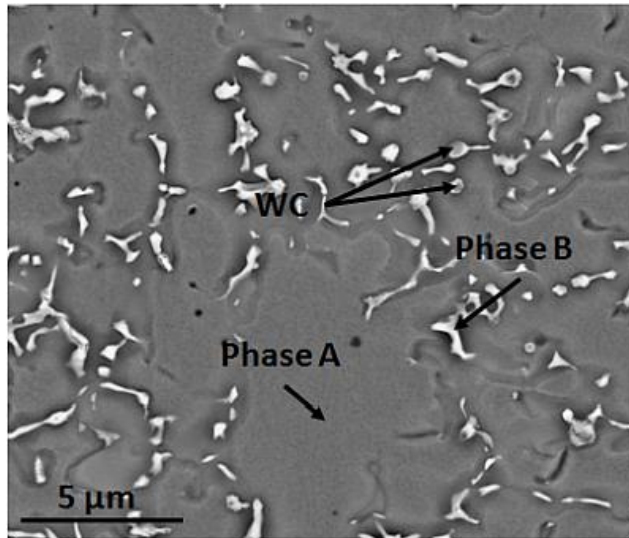


Inconel 625 - 30 wt % WC

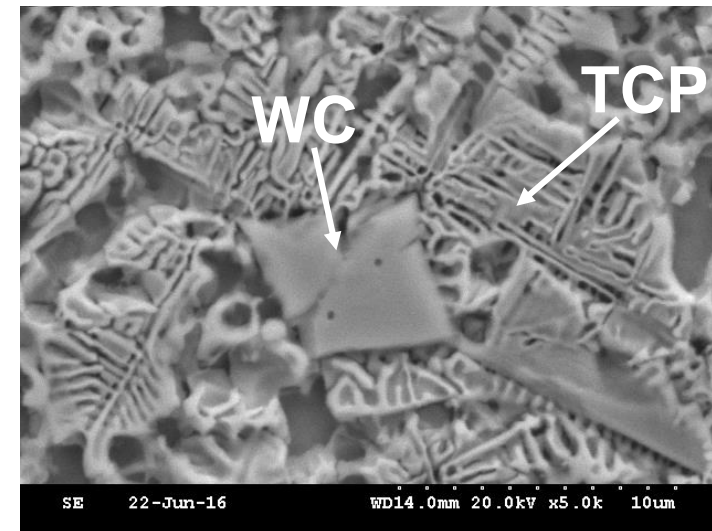
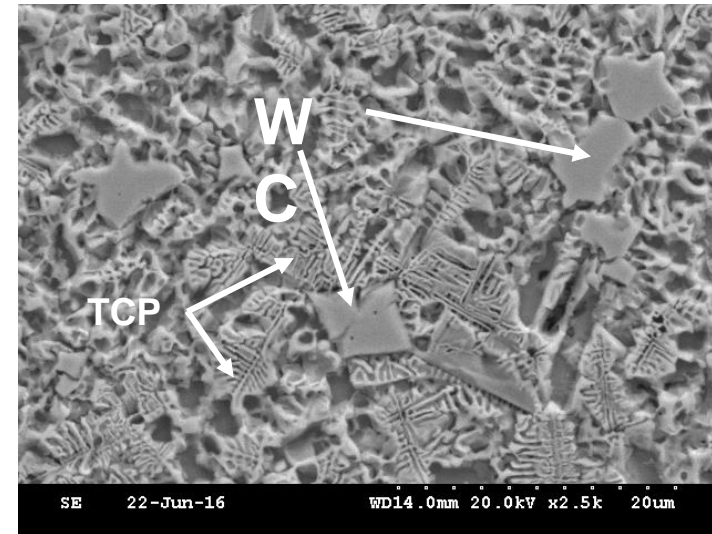


Microstructures of Inconel 625 – WC 0,63μm

Inconel 625 + WC (0.64 μm) composite

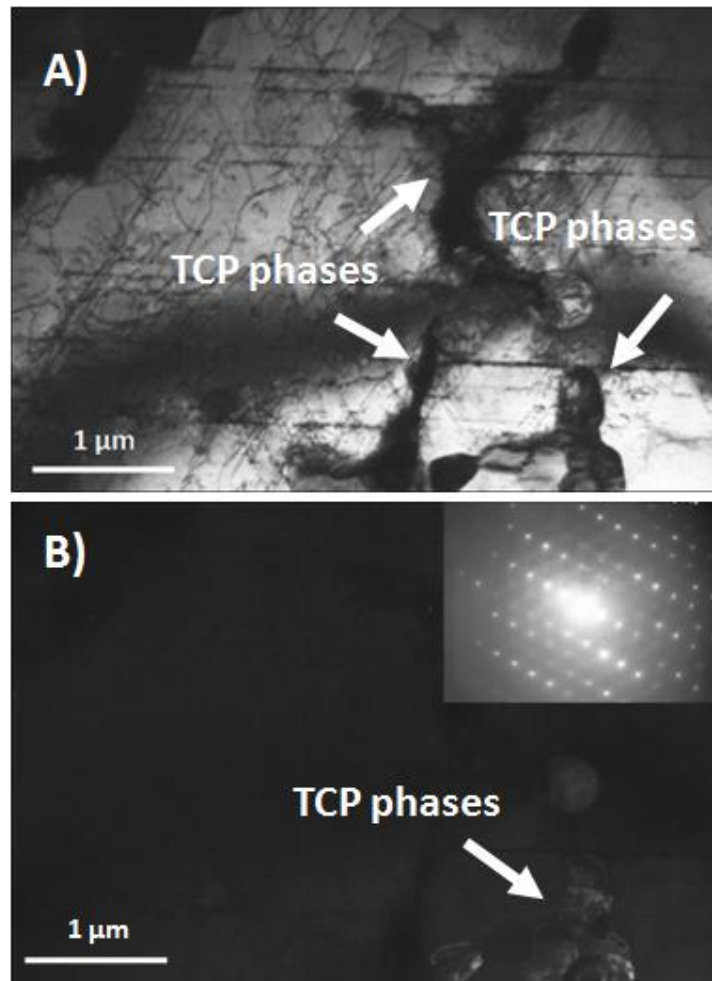


Inconel 625 + WC (6.03 μm) composite

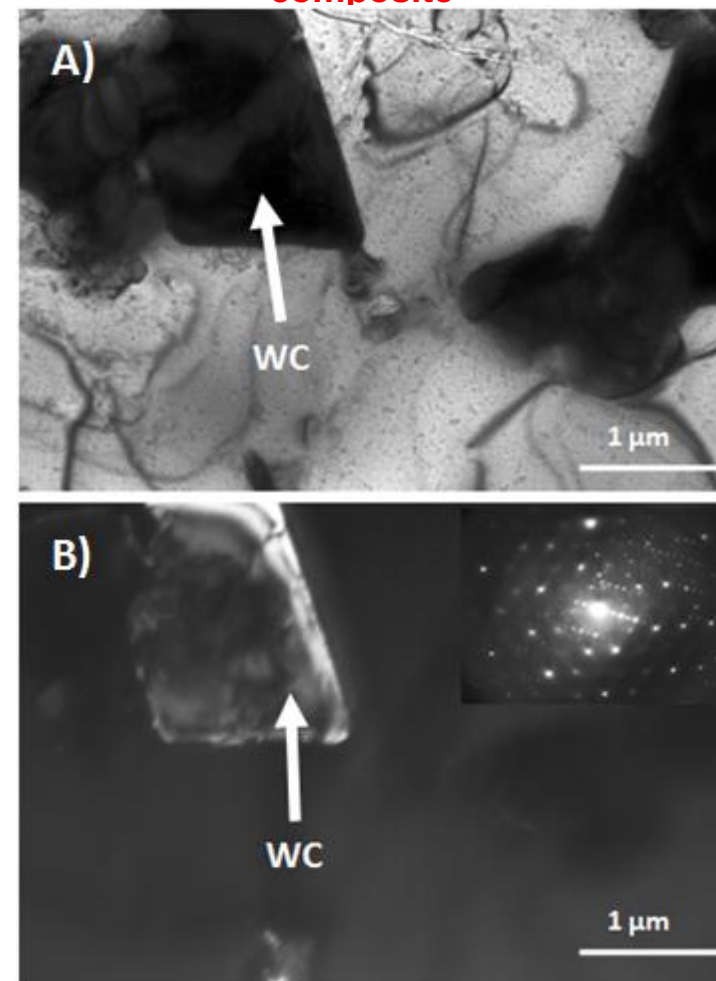


TEM analysis of laser 3D shaped of Inconel – WC composites

**Inconel 625 + WC (0.64 μm)
composite**



**Inconel 625 + WC (6.03 μm)
composite**



3D shaping of silica „hollow fibre”

$$V_{Total} = V_{vdW} + V_{elect} + V_{steric}$$

$$V_{vdW} = -\frac{A_H r}{6\pi x} \quad x \ll r$$

$$A = a \left(\frac{\epsilon_m - \epsilon_p}{\epsilon_m + \epsilon_p} \right)^2 + b \frac{(n_m^2 - n_p^2)^2}{(n_m^2 + n_p^2)^{3/2}}$$

V_{Total} - total energy balance of dispersion

x : distance

r : particle radius

A_H : effective Hamaker constant

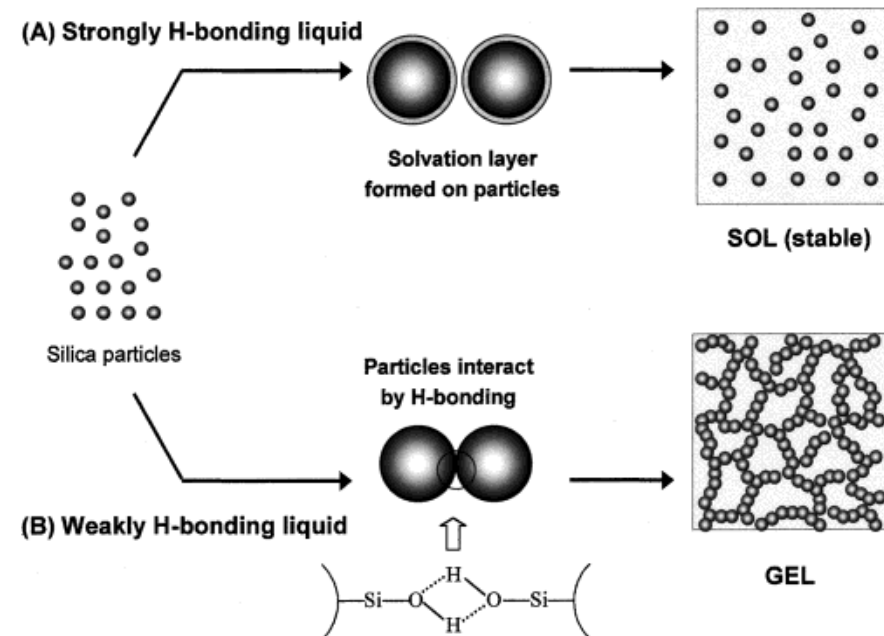
ϵ -dielectric constant (m-monomer,p-particle)

n -refractive index (m-monomer p-particle)

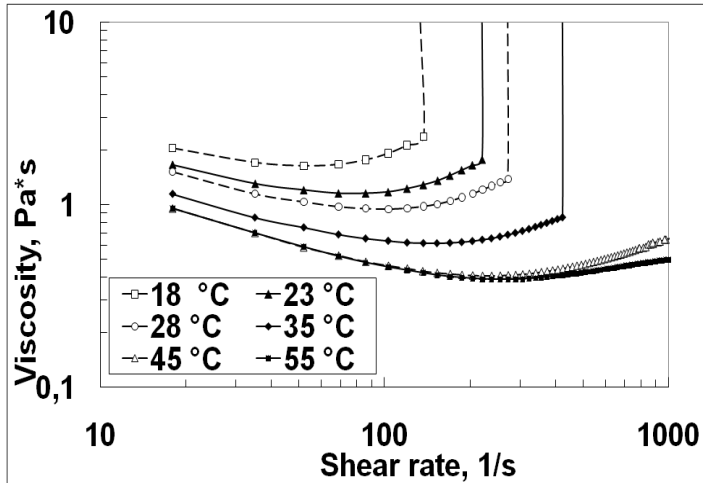
Hydrophylic monomers (monoacrylates with –OH groups)
high maximum concentration of powder, shear thickening behavior after critical shear rate

Hydrophobic monomers (diacrylates)-
very low maximum solid loading (shear thinning behavior at these concentration)

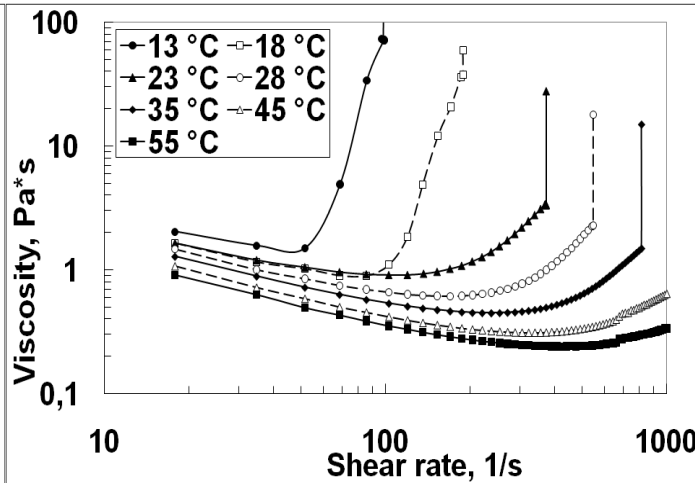
Raghavan, S. R., Walls, H. J. and Khan, S. A., Rheology of silica dispersions in organic liquids: new evidence for solvation forces dictated by hydrogen bonding. *Langmuir*, 2000, **16**, 7920–7930



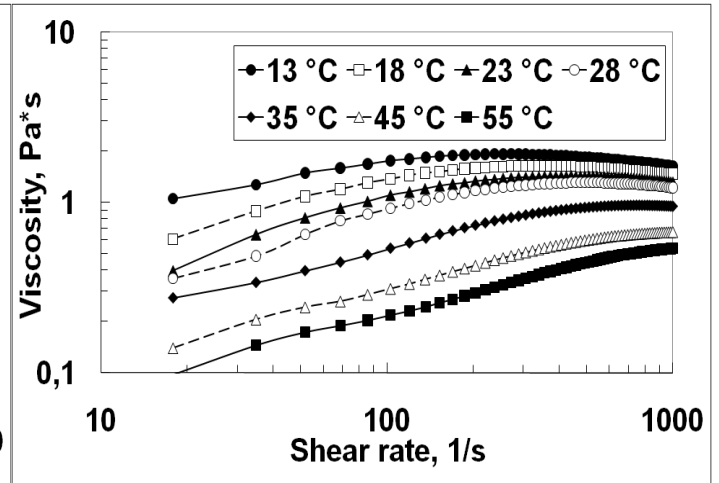
Rheological behaviour of silica dispersion for 3D shaping



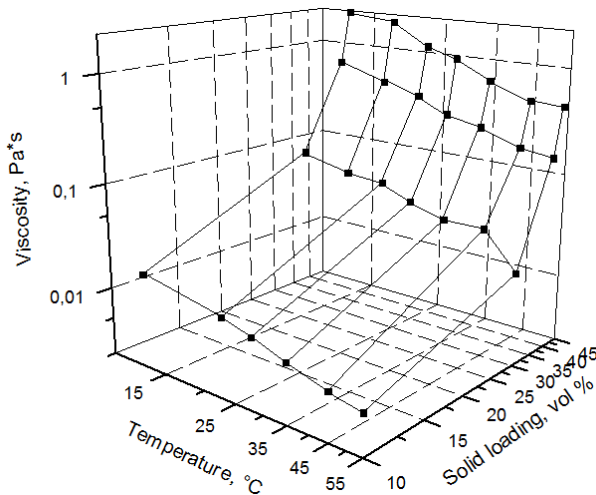
43 % obj. nanokrzesionki w PEG200DA / 2-HEA



54 % obj. krzesionki 0,25 mikrometra w PEG200DA /2-HEA

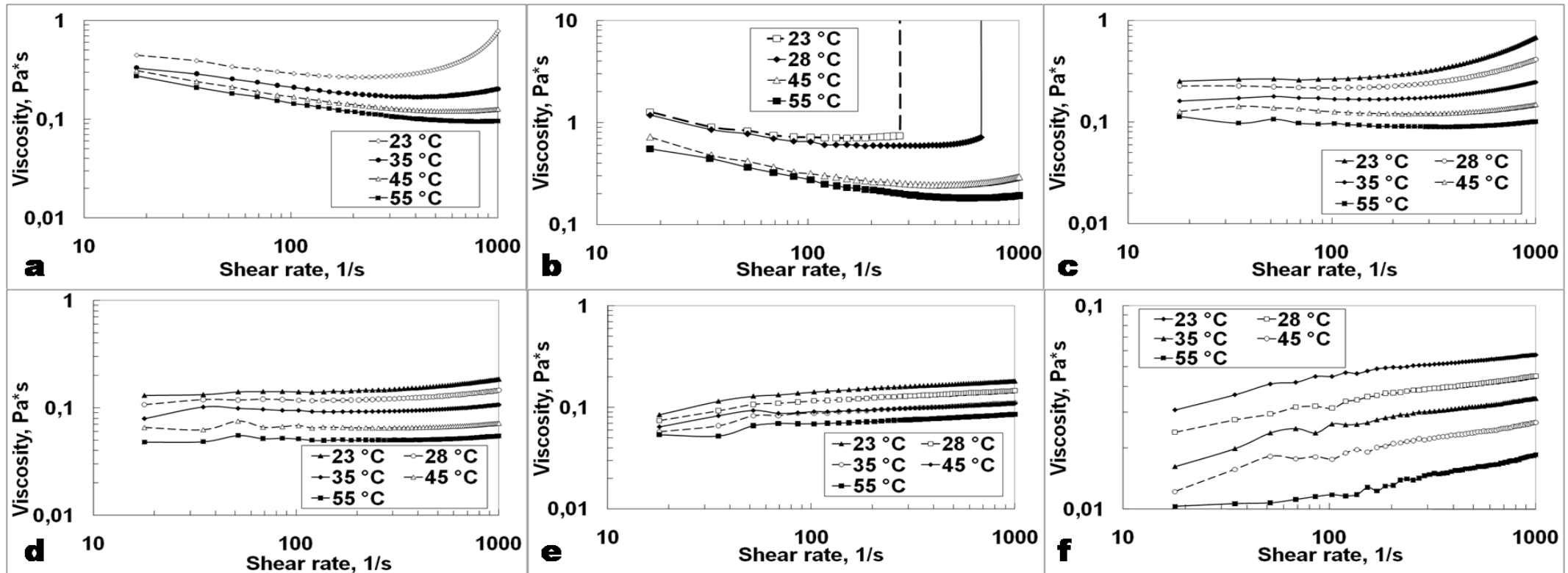


60 % obj. mikrokrzesionki w PEG200DA / 4-HBA



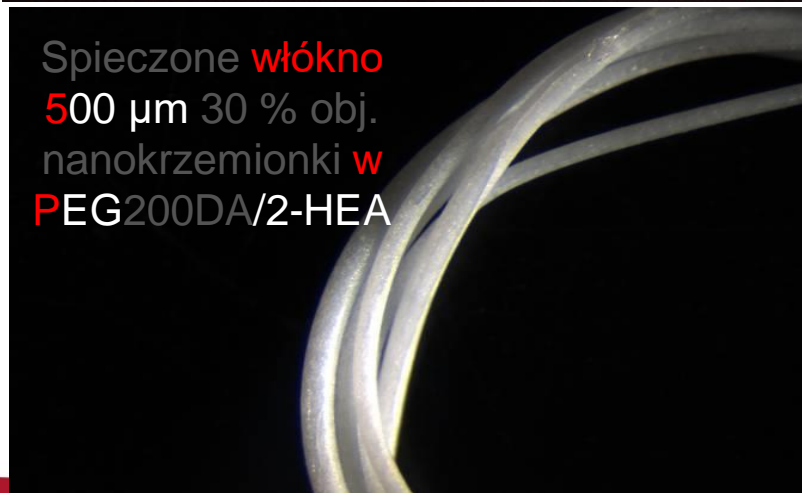
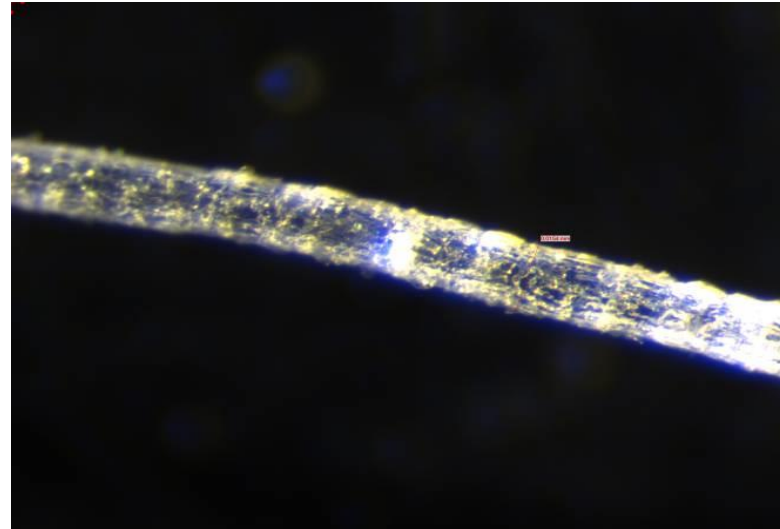
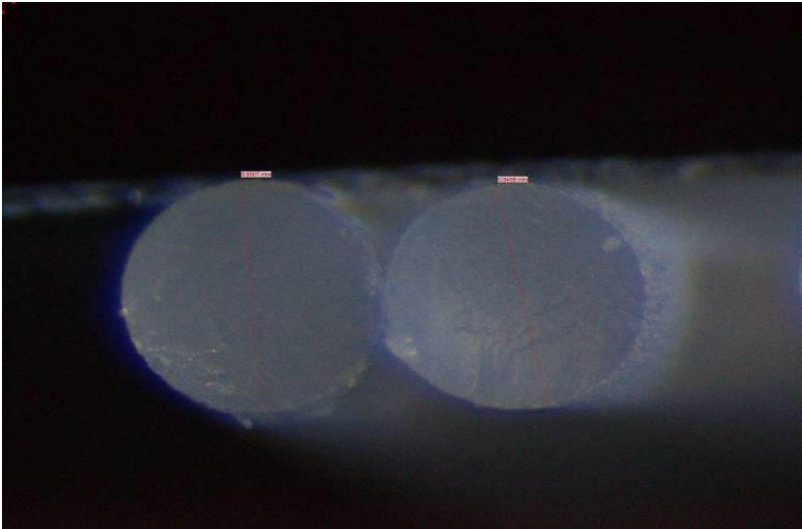
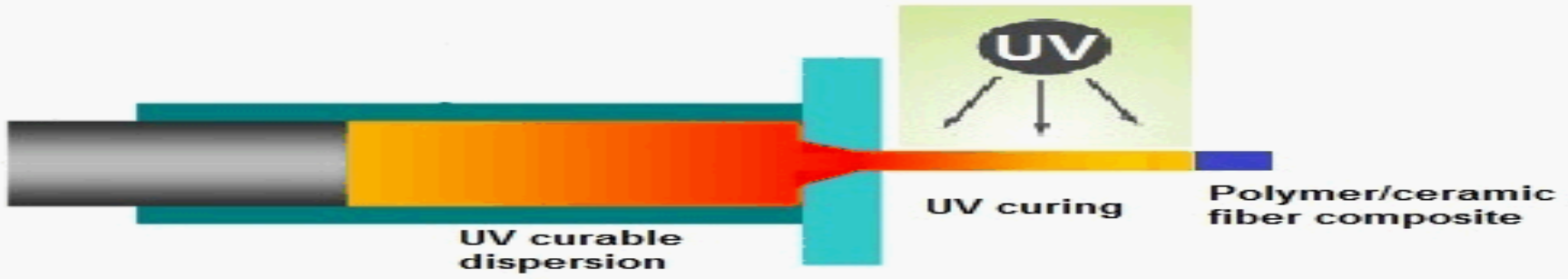
Temperature influence on viscosity of silica dispersions

Rheological behaviour of silica dispersion for 3D shaping

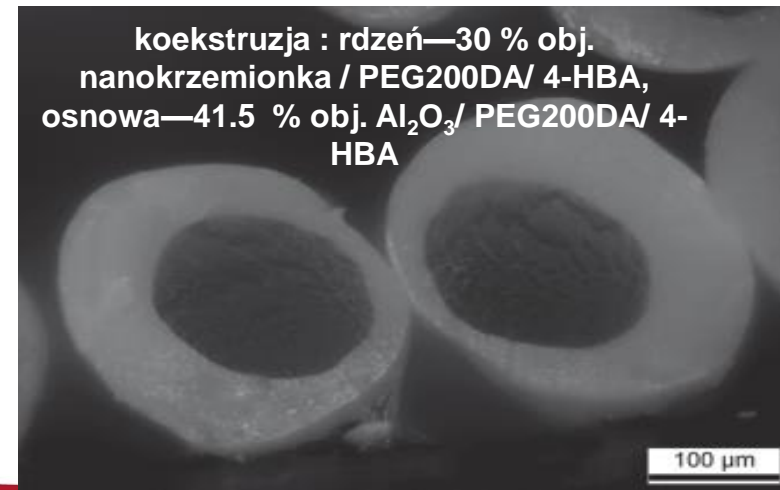


- a) 40 % obj. "nano" + 5 % obj. "mikron", b) 40 % obj. "nano" + 10 % obj. "mikron", c) 30 % obj. "nano" + 20 % obj. "mikron",
 d) 25 % obj. "nano" + 25 % obj. "mikron", e) 15 % obj. "nano" + 35 % obj. "mikron", f) 10 % obj. "nano" + 35 % obj. "mikron",

Maciej Woźniak, Dariusz Kata, Thomas Graule, UV Curable silica Dispersions for Rapid Prototyping Applications, J. European Ceramic Soc. 2012

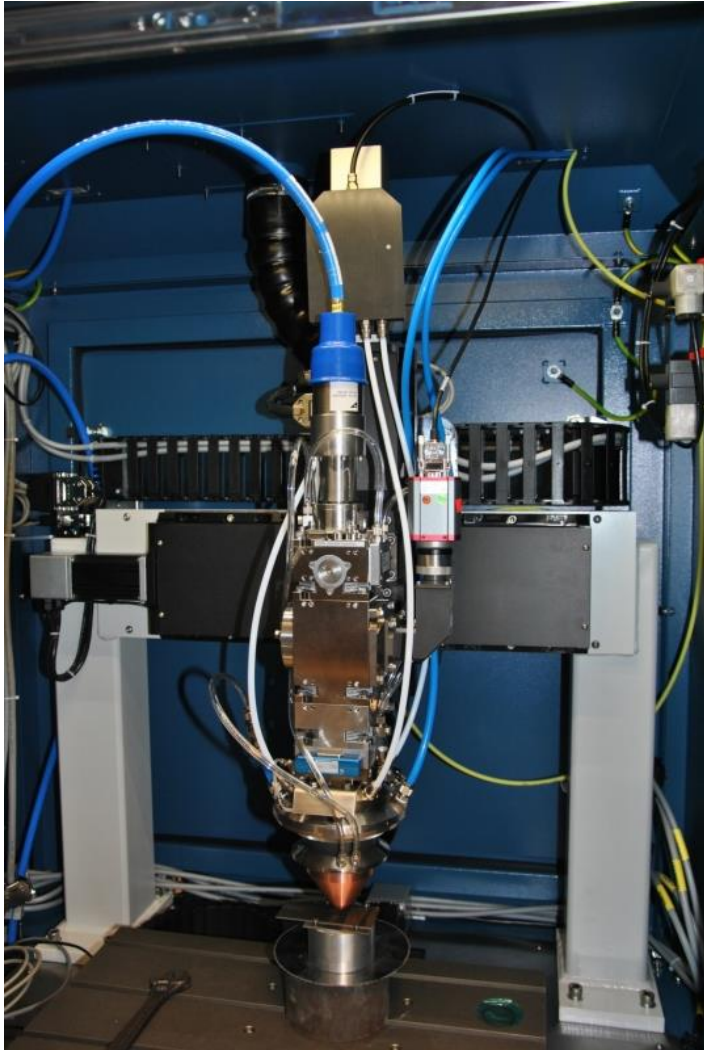


Spieczone włókno
500 μm 30 % obj.
nanokrzemionki w
PEG200DA/2-HEA

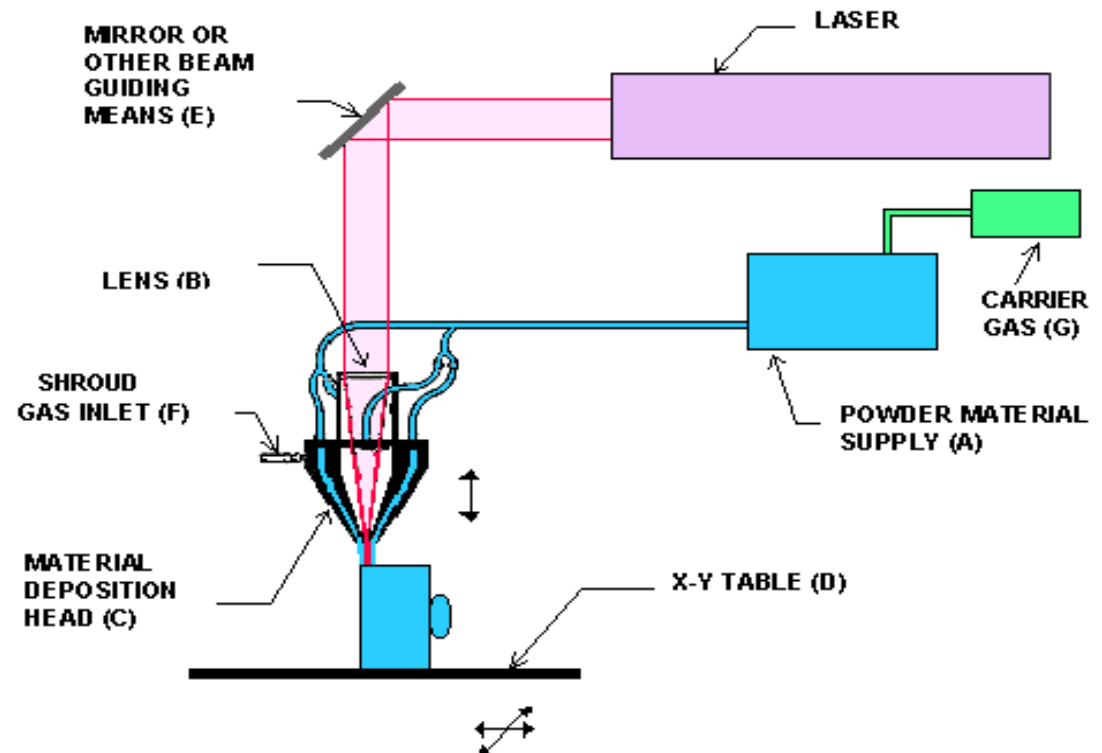


koekstruzja : rdzeń—30 % obj.
nanokrzemionka / PEG200DA/ 4-HBA,
osnowa—41.5 % obj. Al_2O_3 / PEG200DA/ 4-
HBA

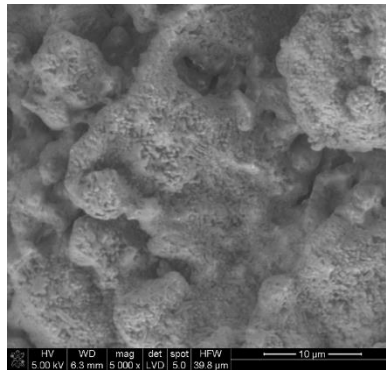
AGH Laboratory of Laser Processing of Ceramic Materials



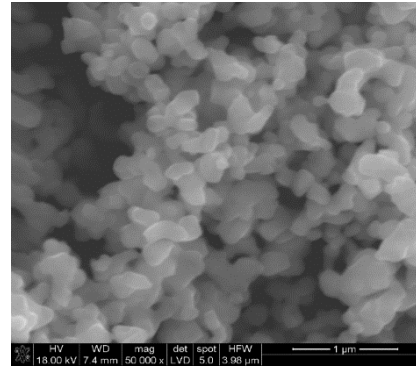
- Hybrid apparatus for Selective Laser Sintering, laser cladding, surface ablation, welding, cutting and SHS reactions
- JK2000FL equipped with ytterbium doped wire fiber
- Laser beam with wavelength of $1063[\text{nm}] \pm 10[\text{nm}]$



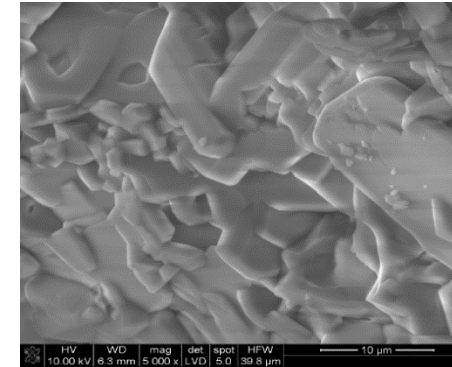
K_{1-x}Na_xNbO₃ (KNN) synthesis solid state reaction



K₂CO₃



Nb₂O₅



Na₂CO₃

Rotary milling for 12 hours or dry homogenization

solid state synthesis of K_{0,5}Na_{0,5}NbO₃ by heat treatment

DTA and XRD

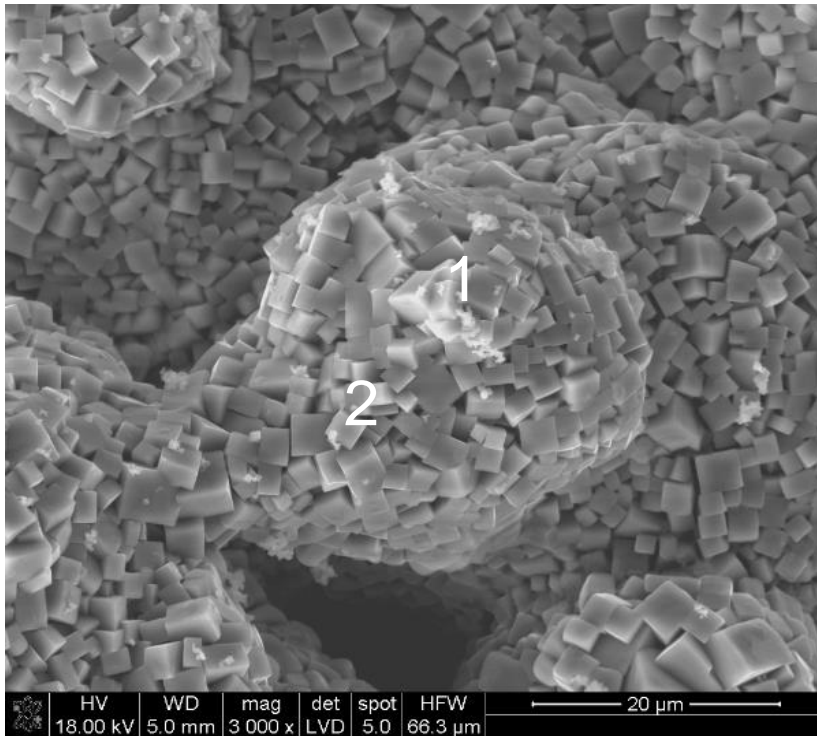
analysis of obtained powders

SEM and EDS

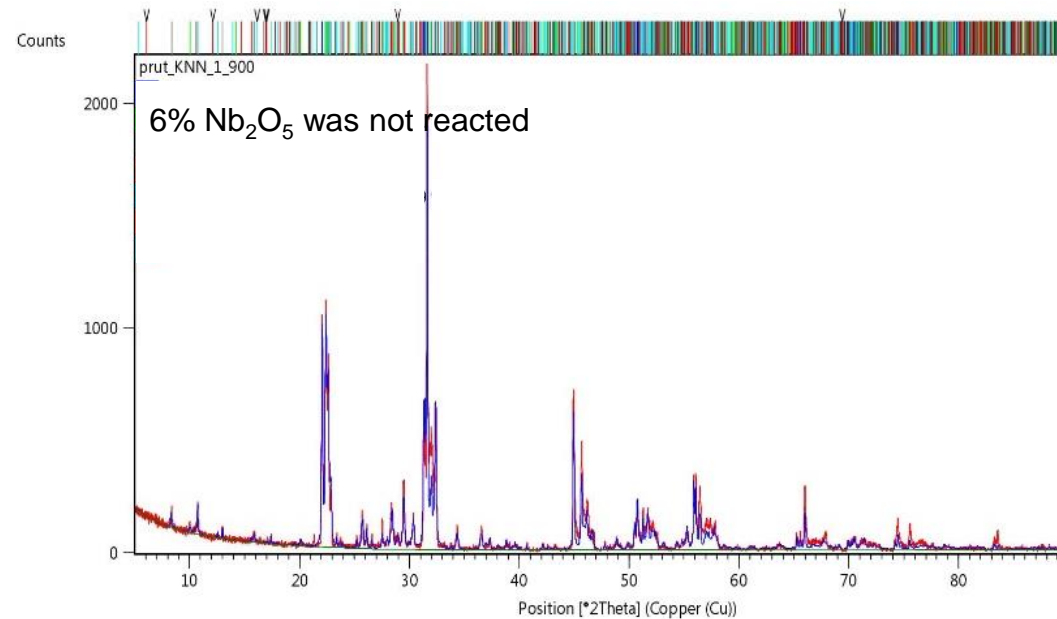
analysis of obtained powders



$K_{1-x}Na_xNbO_3$ (KNN) synthesis solid state reaction at 900°C



Morphology by SEM

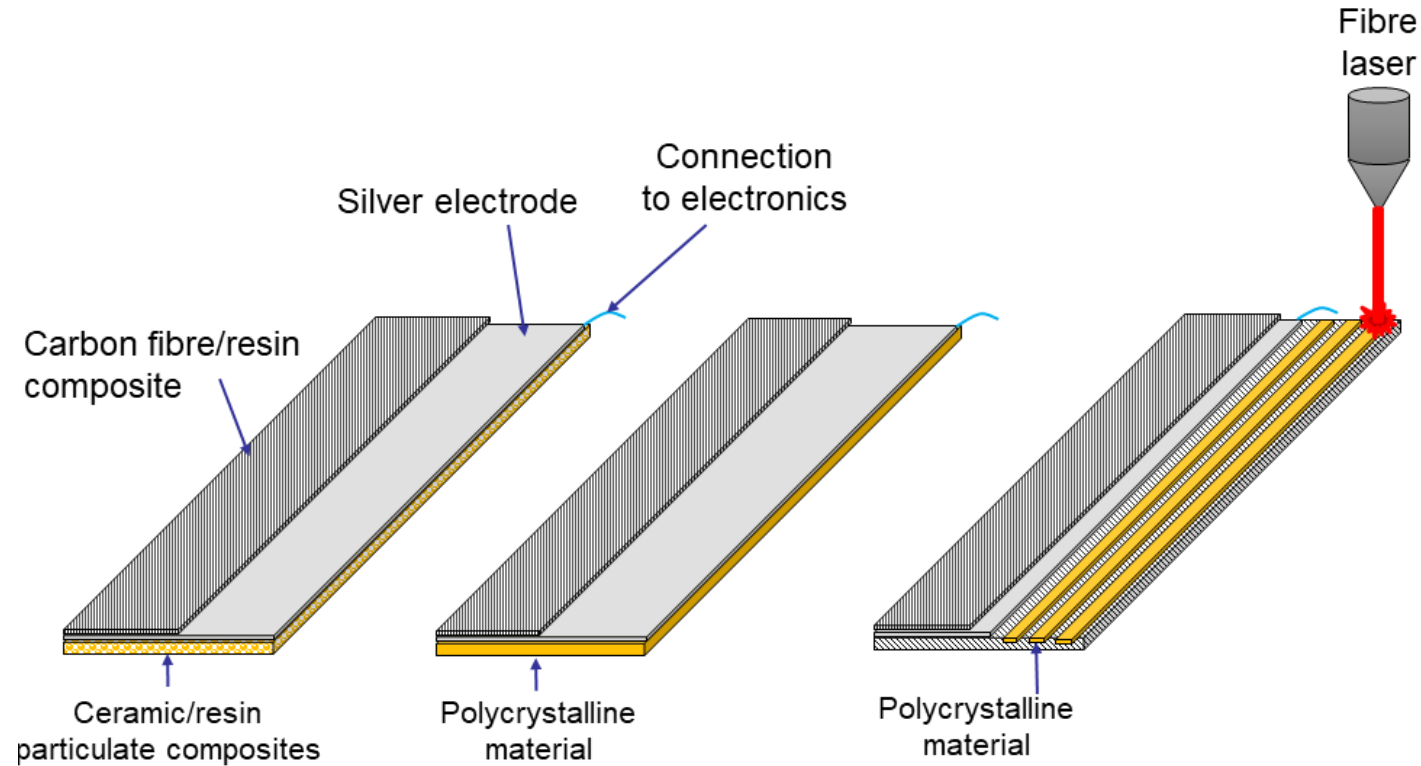


XRD analysis

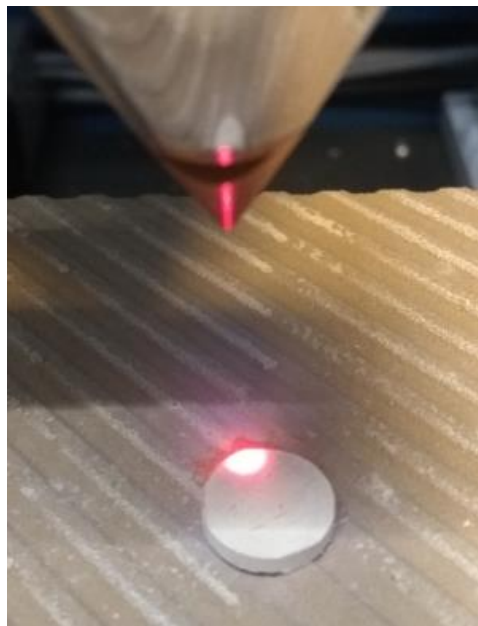
| Point | Mass content [%] | | | |
|-------|------------------|------|-------|------|
| | O | Na | Nb | K |
| 1 | 24,67 | 5,29 | 52,30 | 3,02 |
| 2 | 16,01 | 5,92 | 56,03 | 3,29 |

EDS analysis

Additive Manufacturing of (KNN) and PZT piezoelectric samples



Additive Manufacturing of (KNN) and PZT piezoelectric samples



PZT tested sample



PZT Selective
Laser Sintered



KNN Selective
Laser Sintered

Conclusion:

Additive Manufacturing is very useful perspective technology for shaping different materials

Thank you for your attention